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Sarode Vishwanath et al.

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(54) **IN-SITU APPARATUS FOR SEMICONDUCTOR PROCESS MODULE**

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H01L 21/687 (2006.01)

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CPC **H01L 21/68707** (2013.01); **C23C 16/4584** (2013.01); **C23C 16/4585** (2013.01);

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CPC H01L 21/68707; H01L 21/67748; H01L 21/6831; H01L 21/68721; H01L 21/68742;

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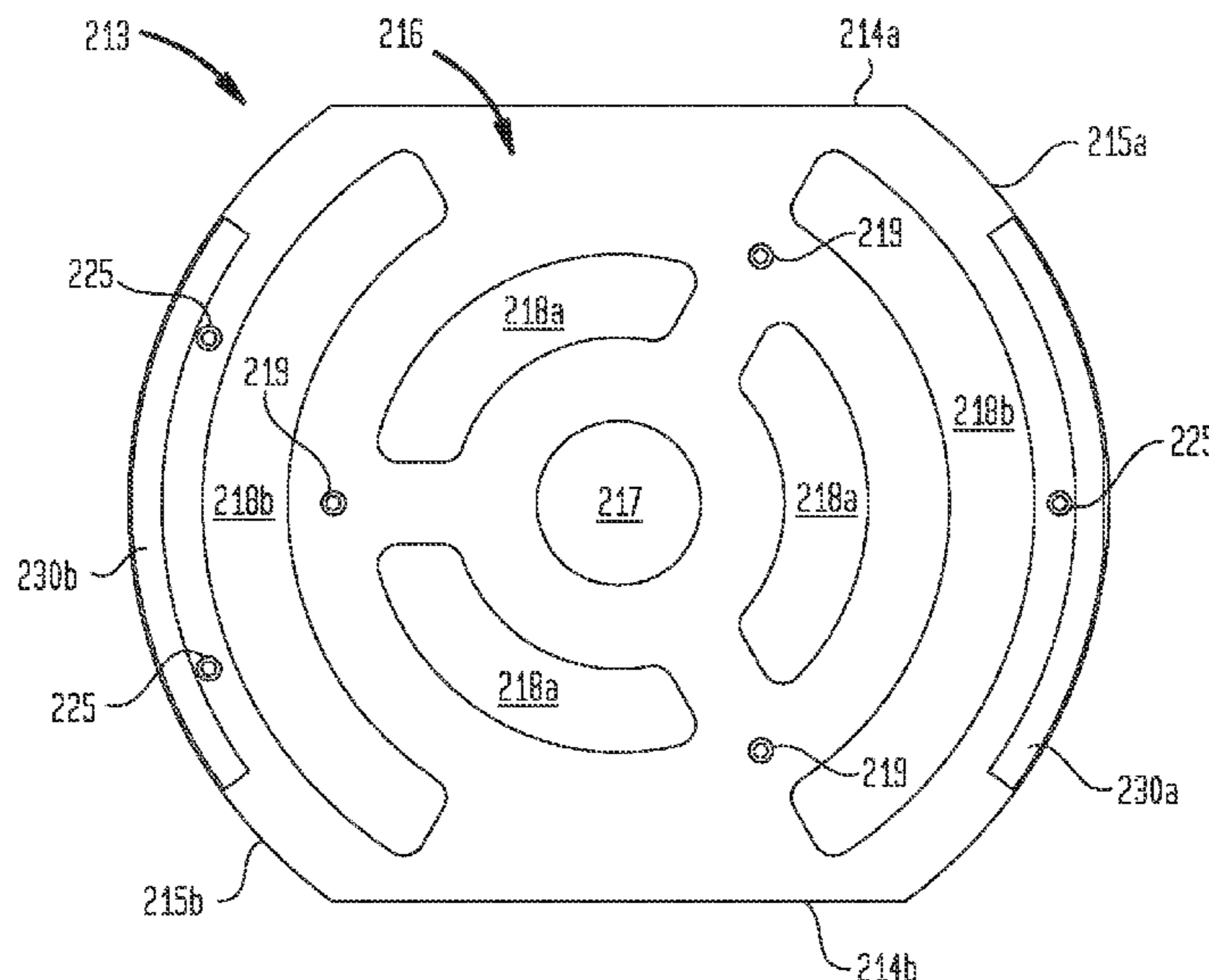
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(57) **ABSTRACT**

Aspects of the present disclosure generally relate to apparatuses and methods for edge ring replacement in processing chambers. In one aspect, a carrier for supporting an edge ring is disclosed. In other aspects, robot blades for supporting a carrier are disclosed. In another aspect, a support structure for supporting a carrier in a degassing chamber is disclosed. In another aspect, a method of transferring an edge ring on a carrier is disclosed.

20 Claims, 14 Drawing Sheets



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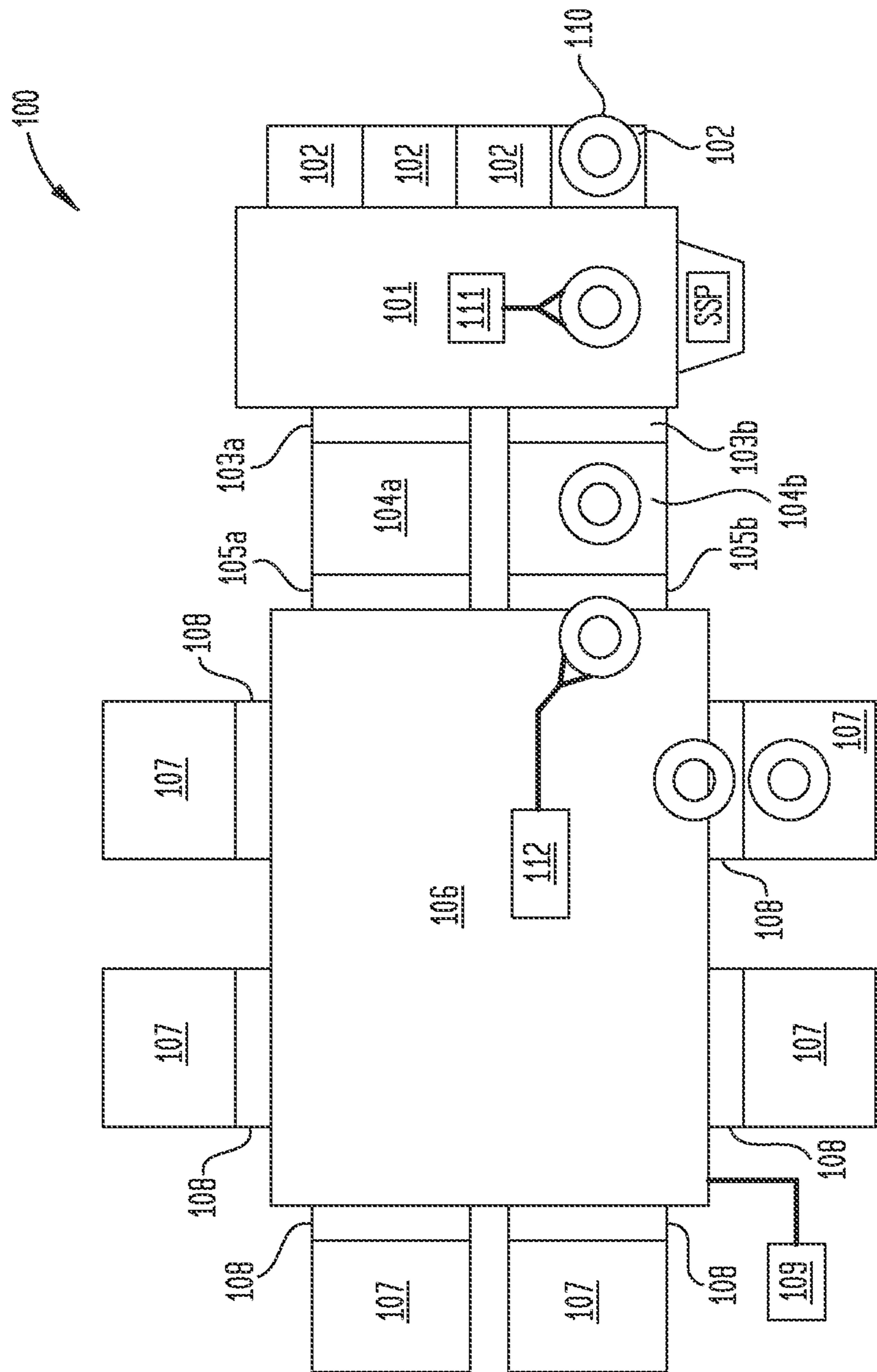


FIG. 1

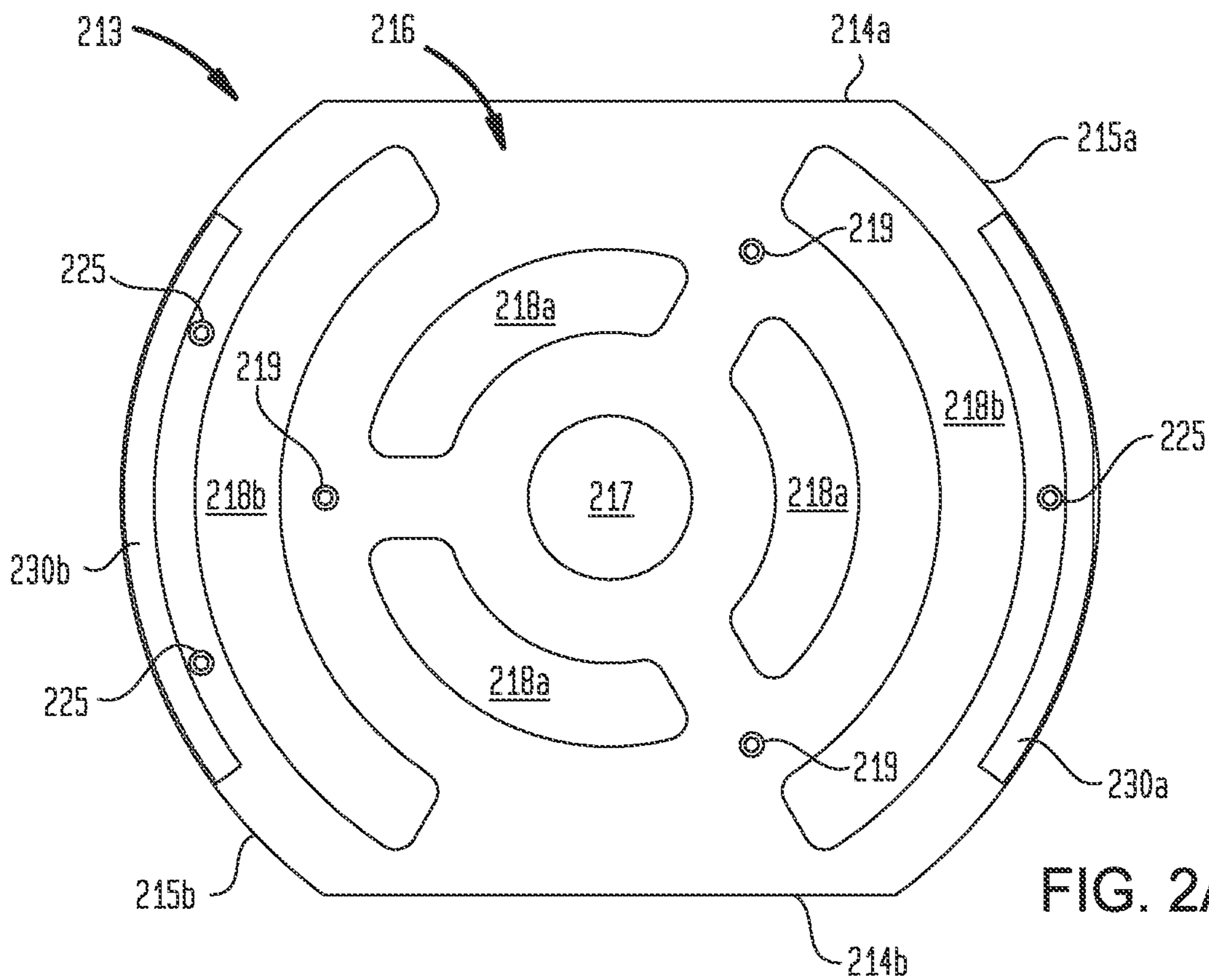


FIG. 2A

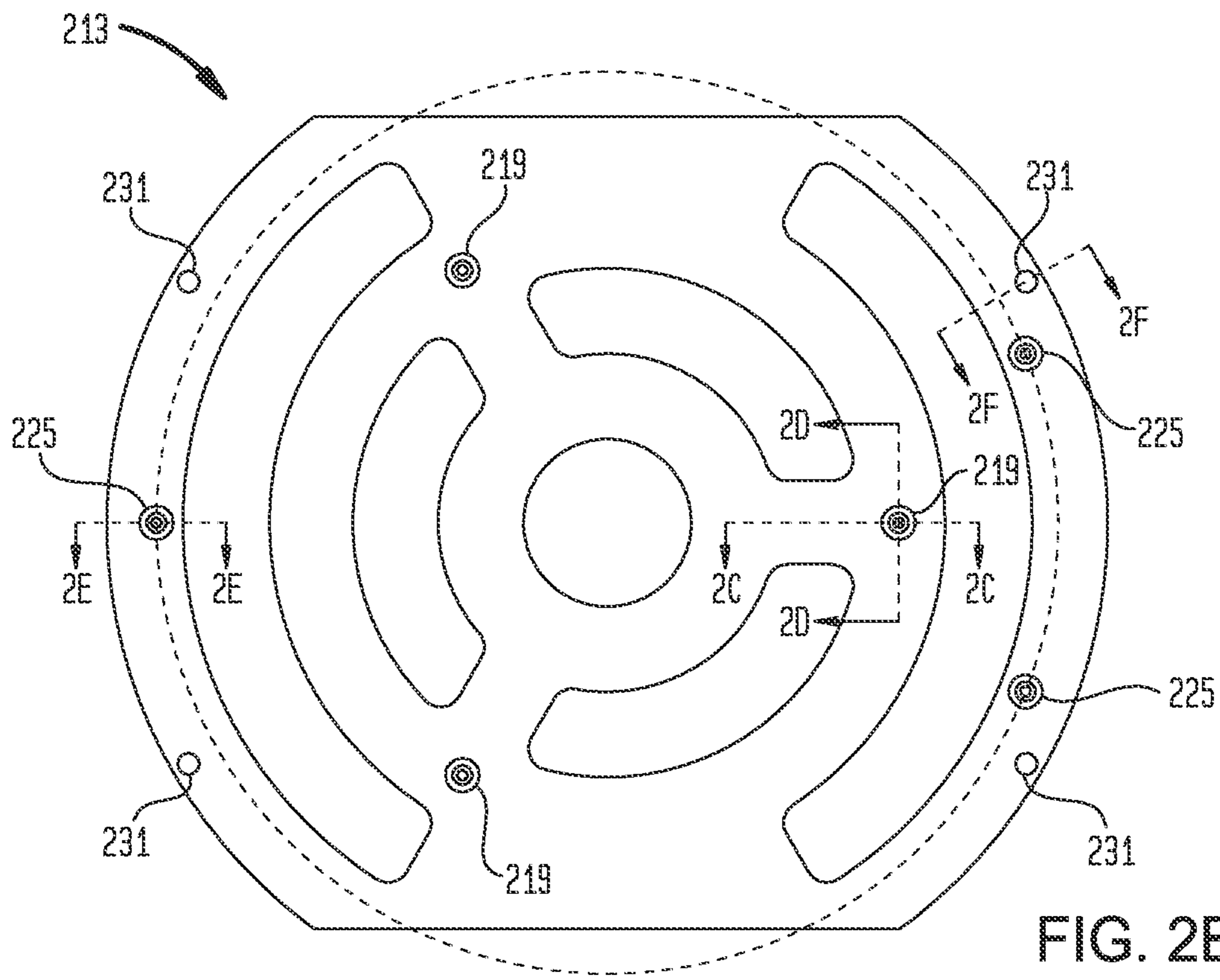


FIG. 2B

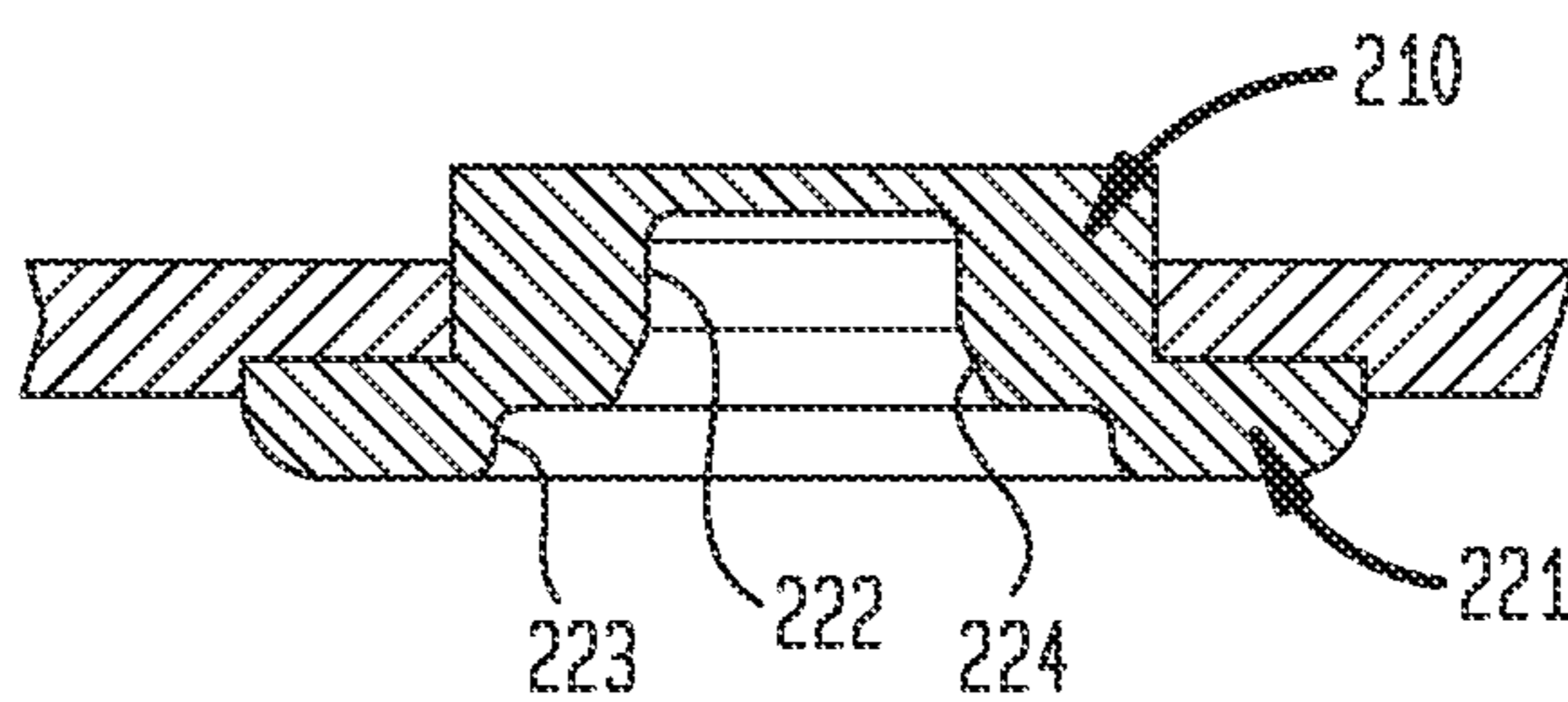


FIG. 2C

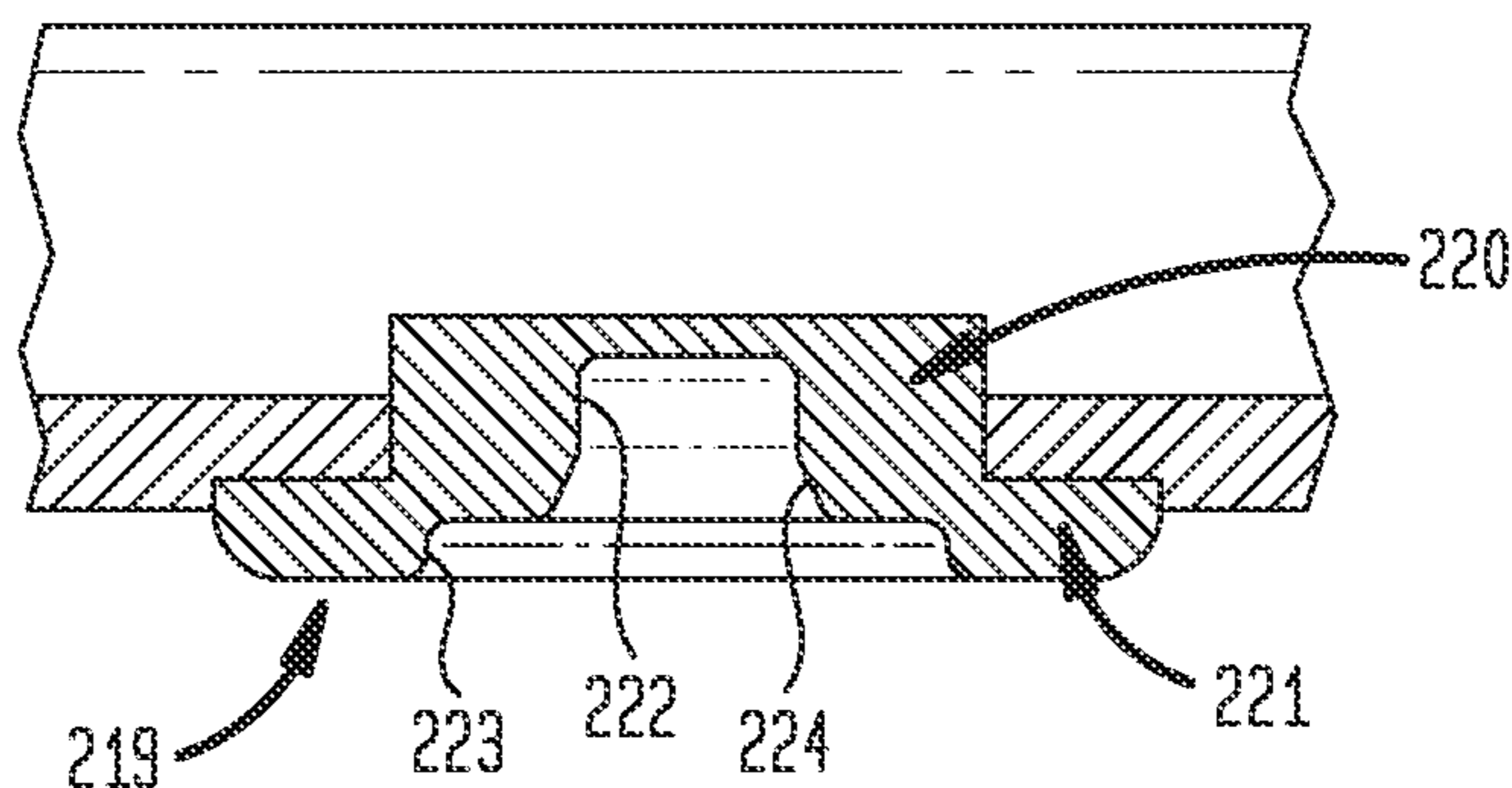


FIG. 2D

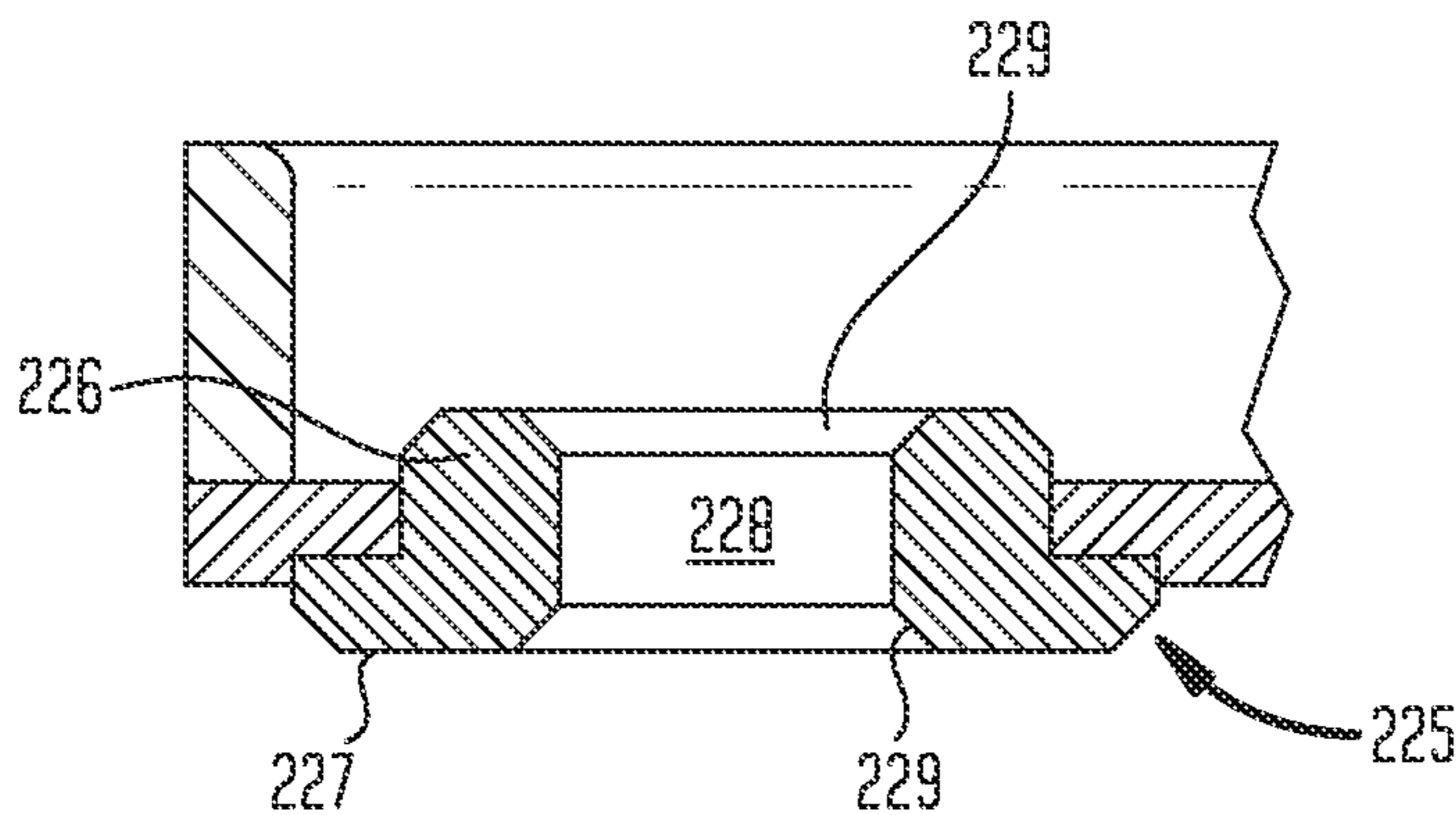


FIG. 2E

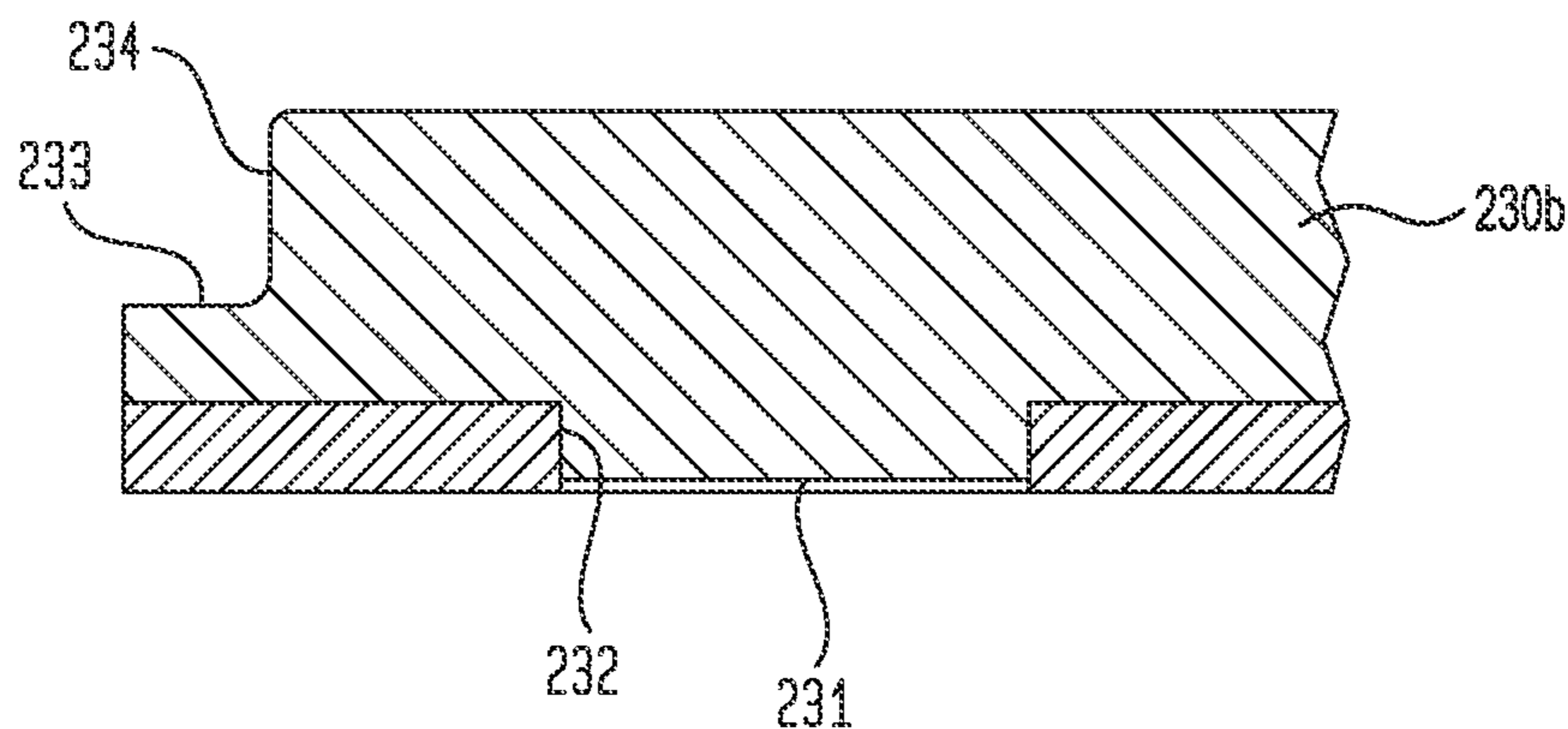


FIG. 2F

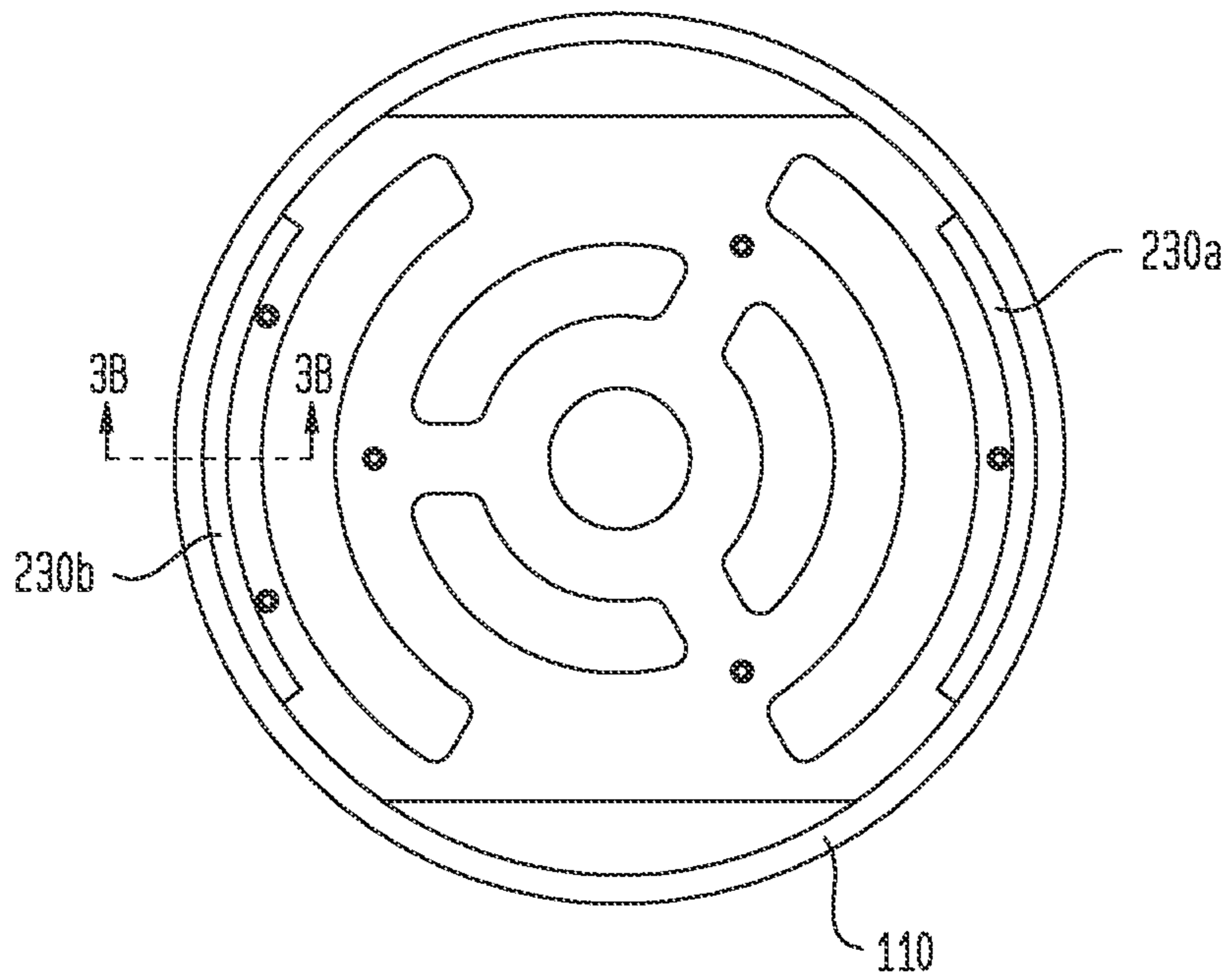


FIG. 3A

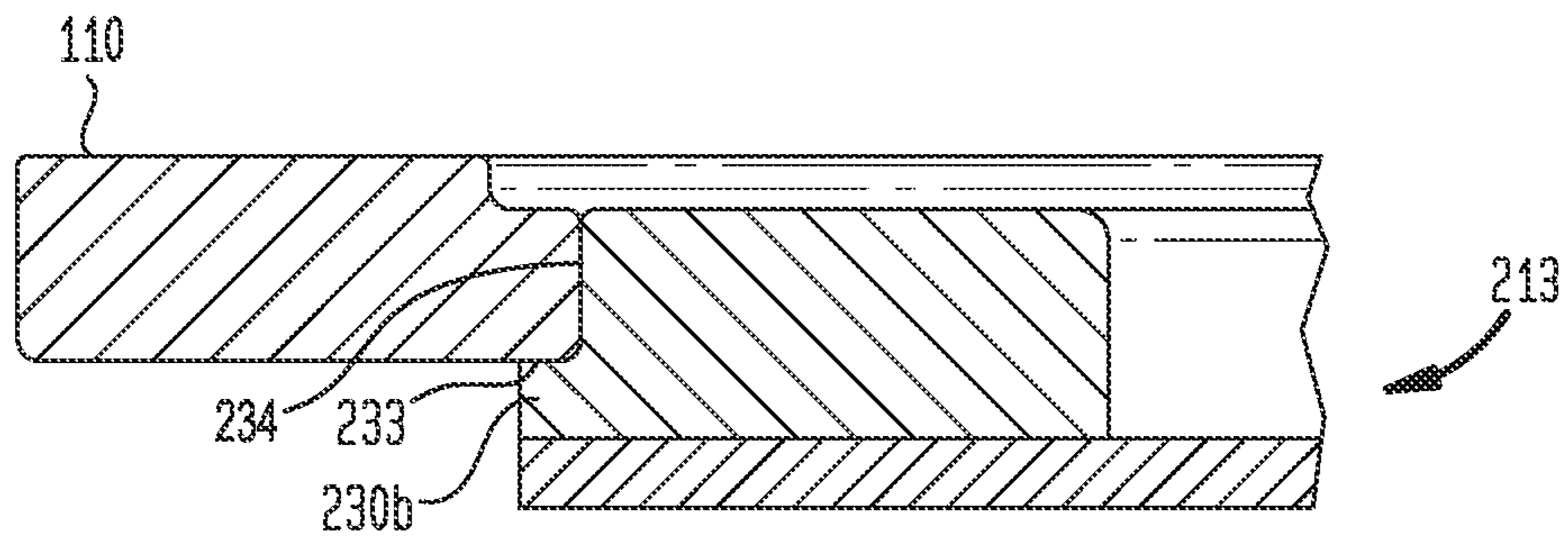


FIG. 3B

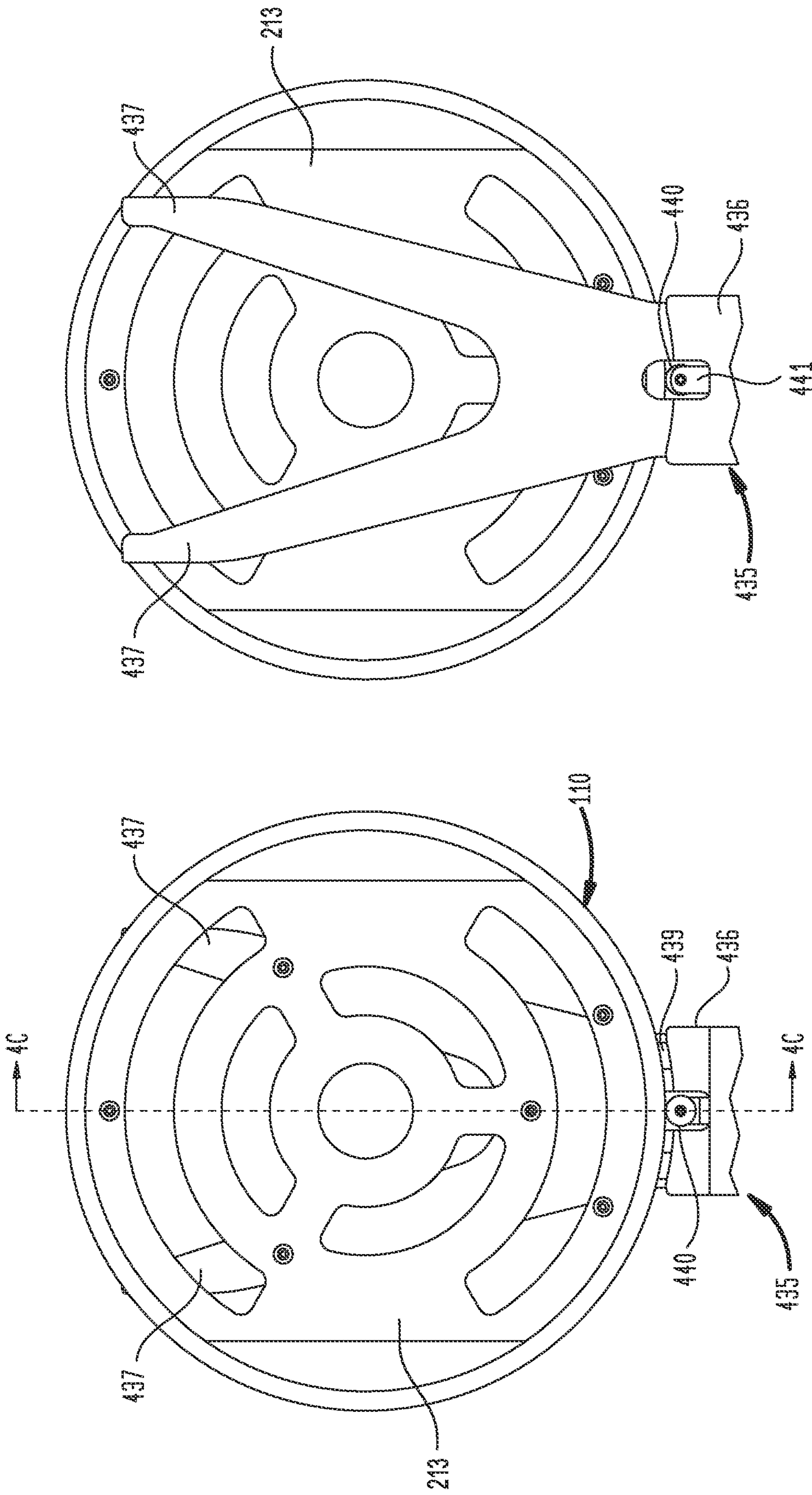


FIG. 4B

FIG. 4A

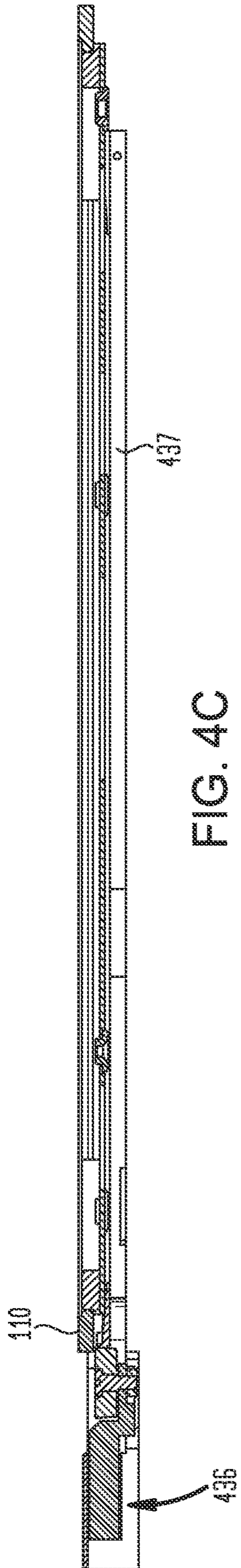


FIG. 4C

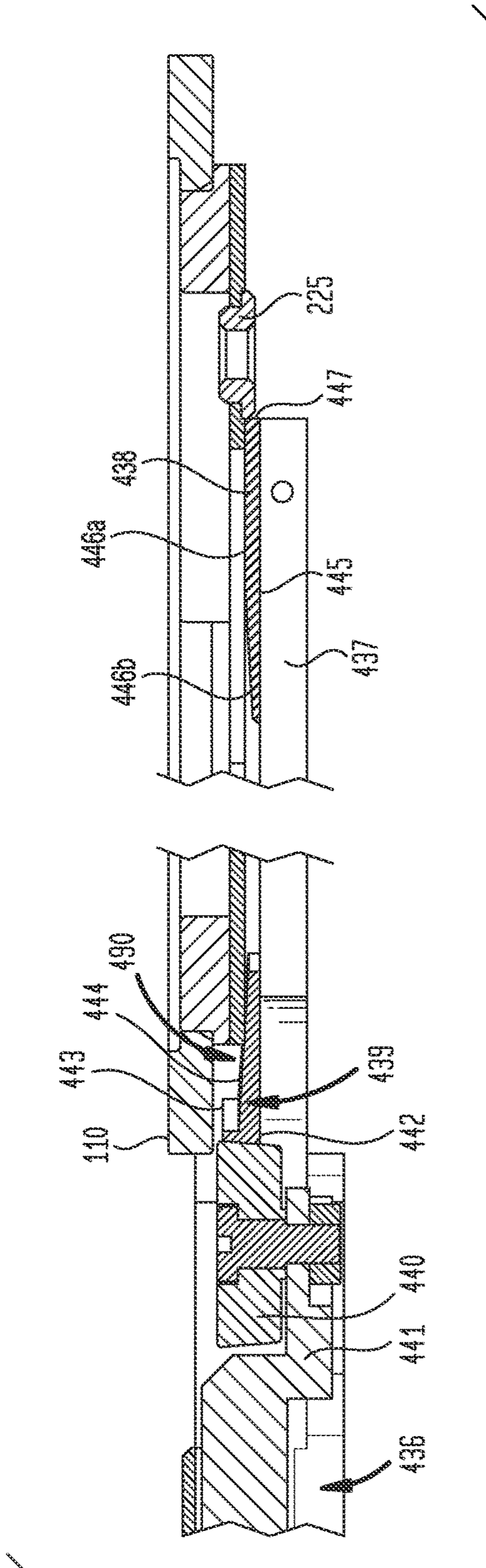


FIG. 4D

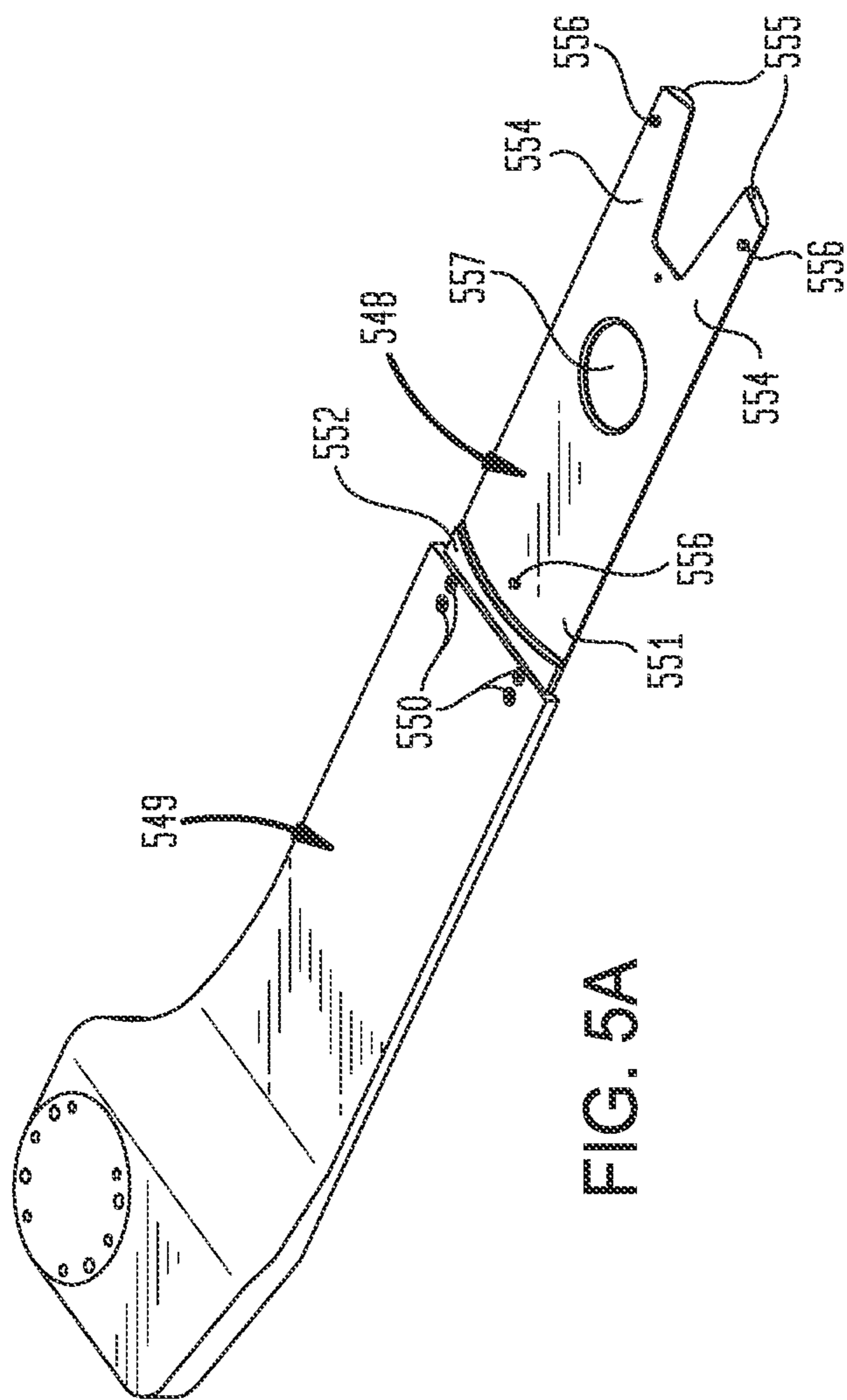


FIG. 5A

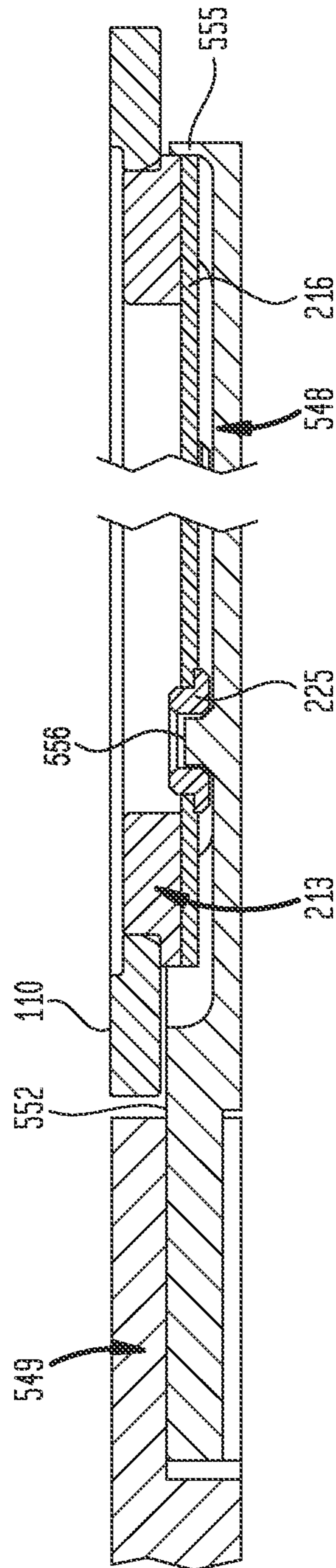


FIG. 5B

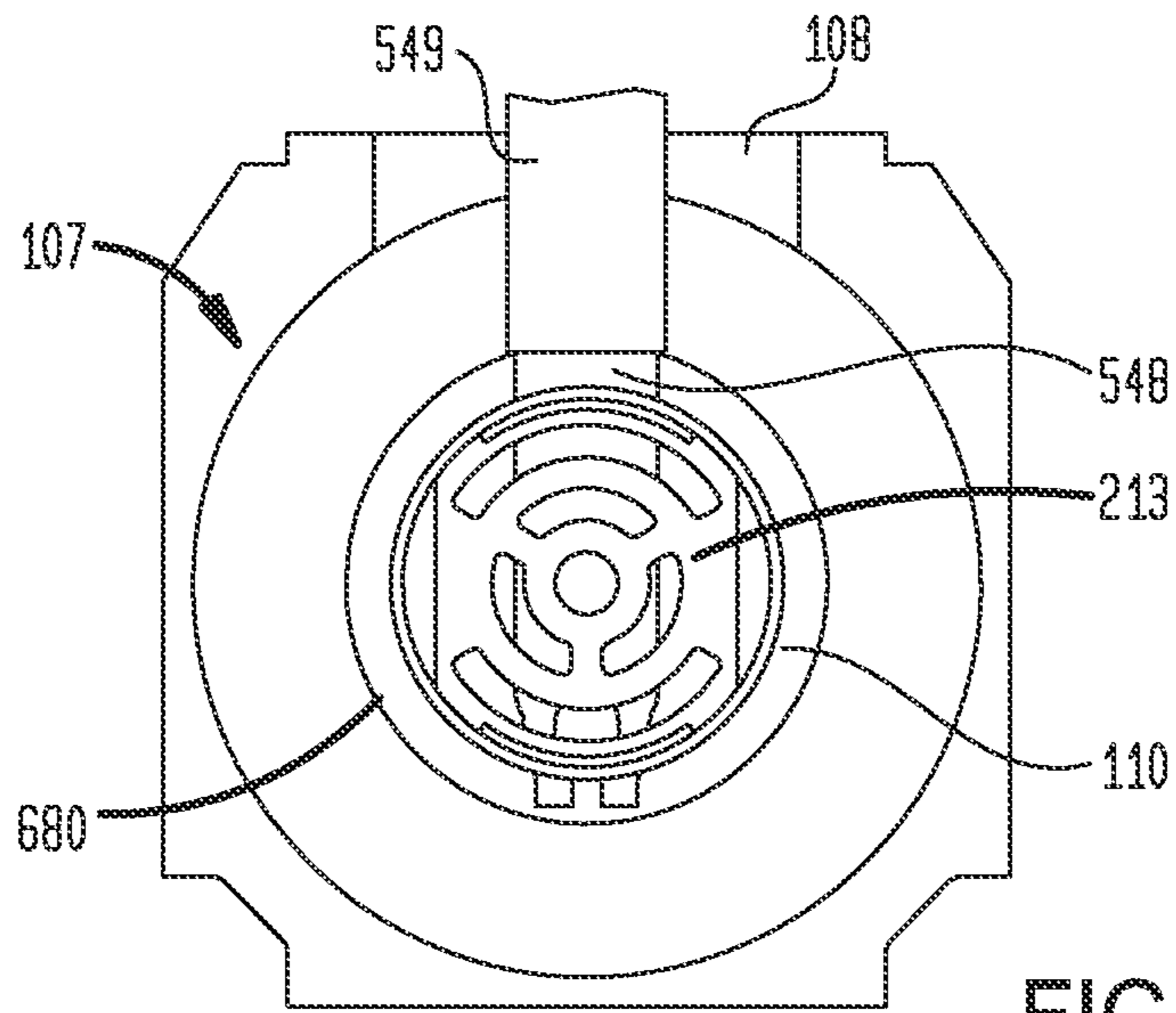


FIG. 6A

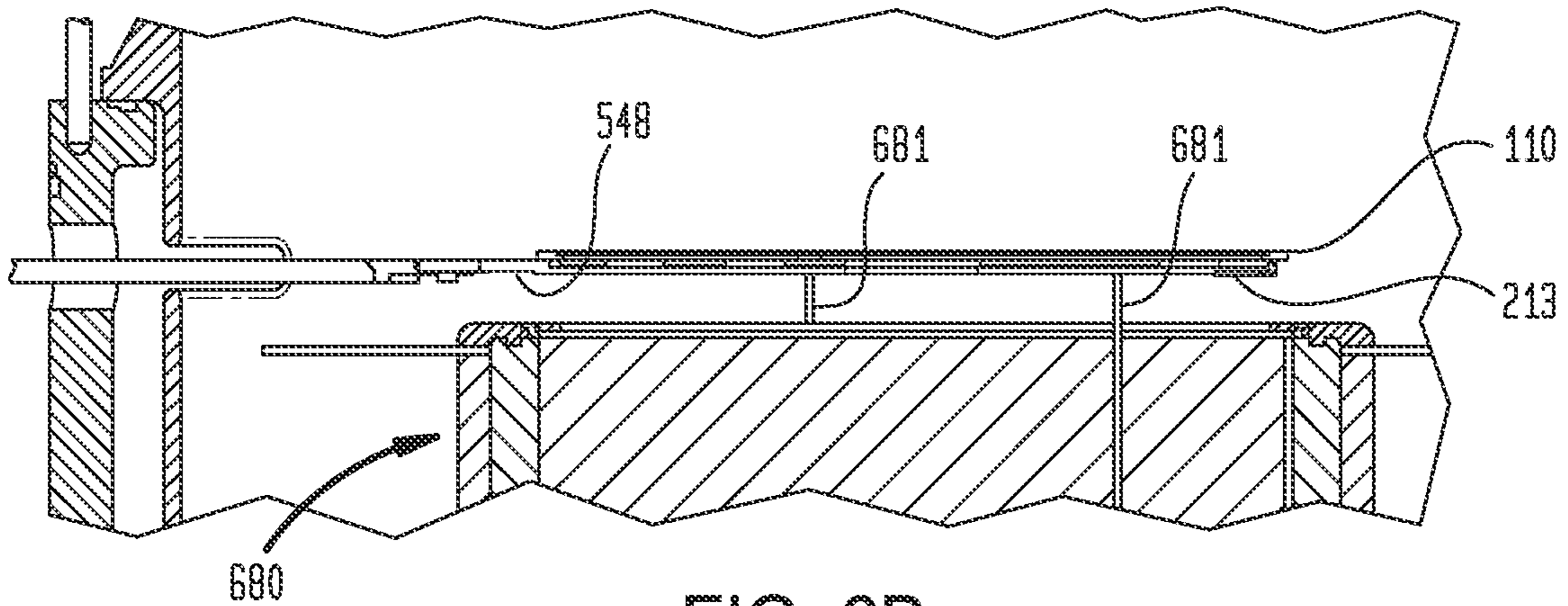


FIG. 6B

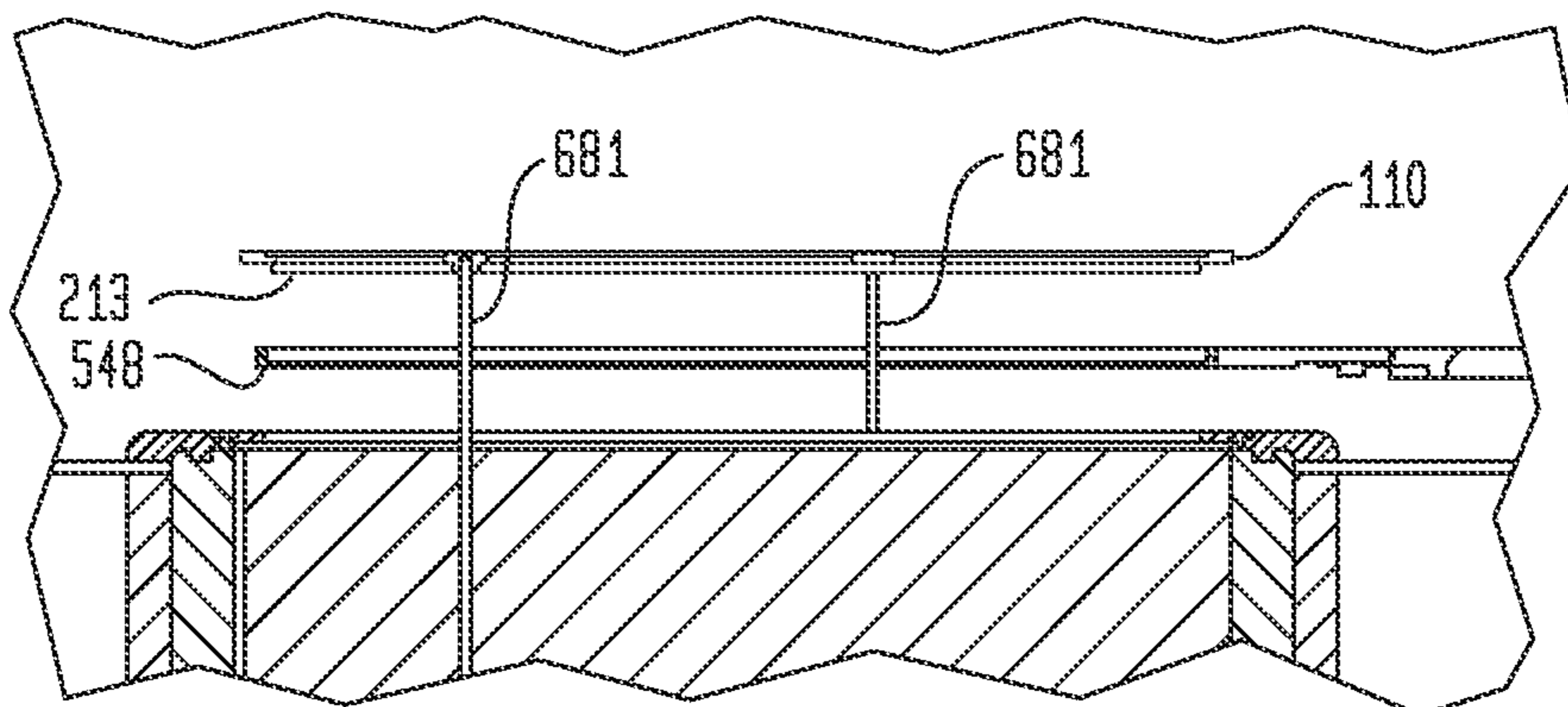


FIG. 6C

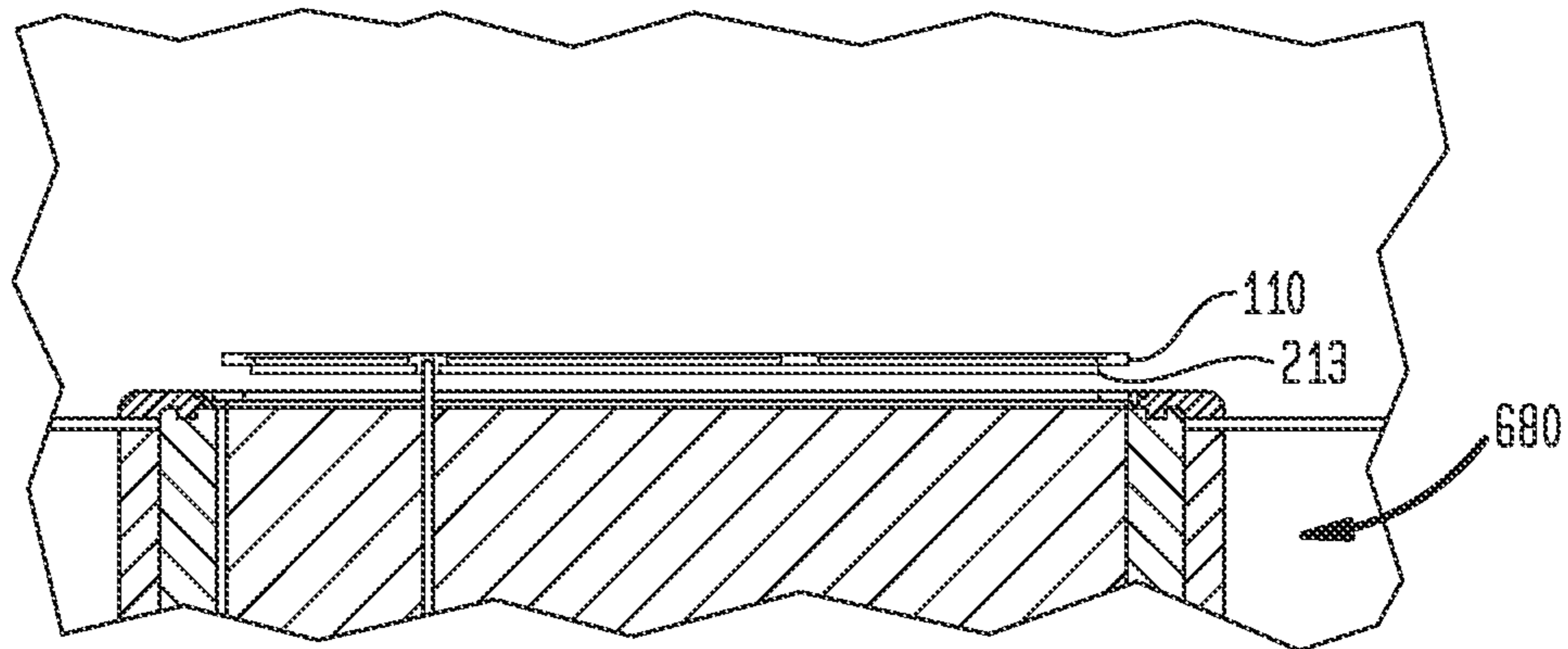


FIG. 6D

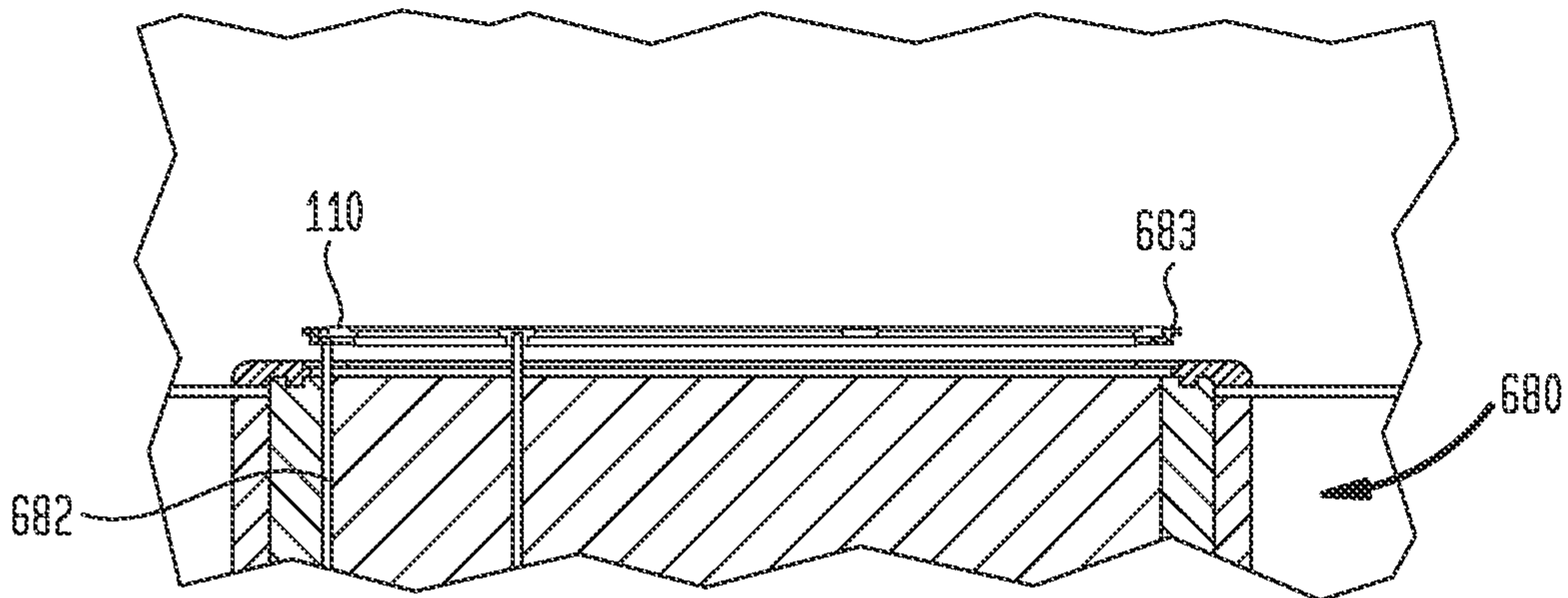


FIG. 6E

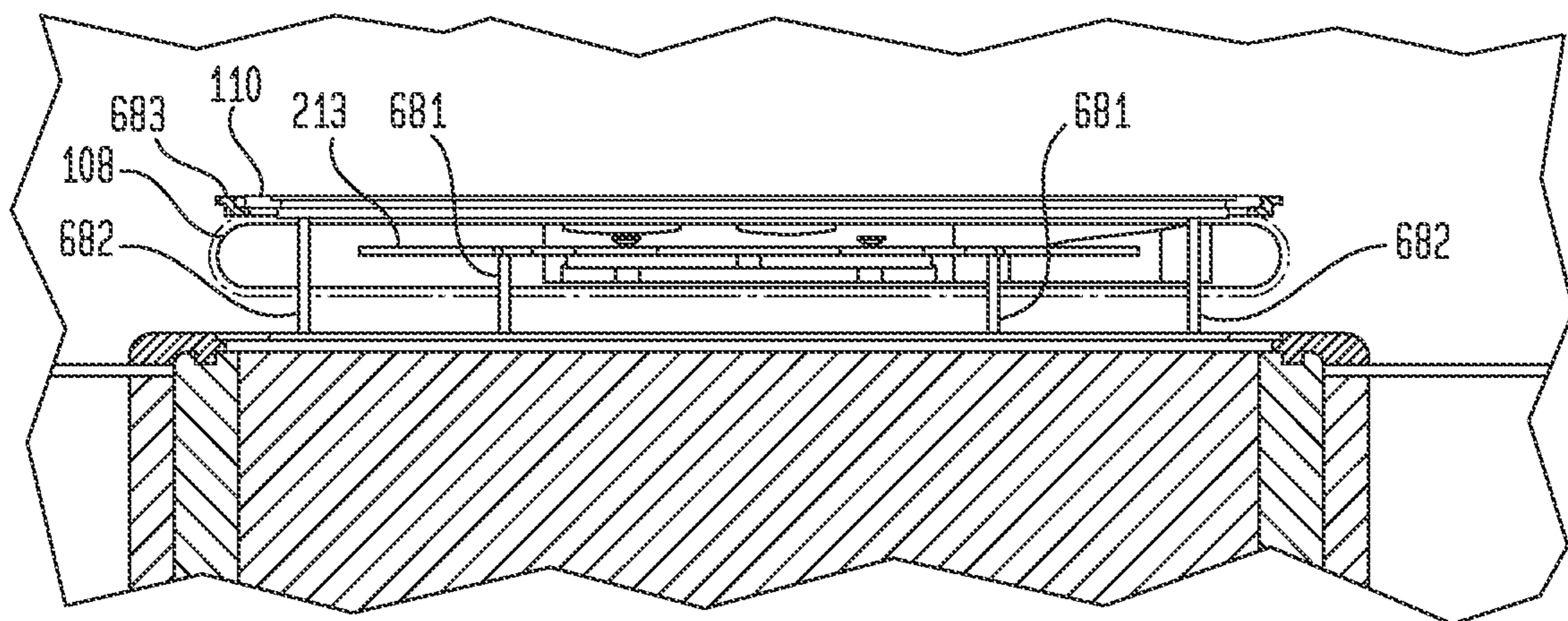


FIG. 6F

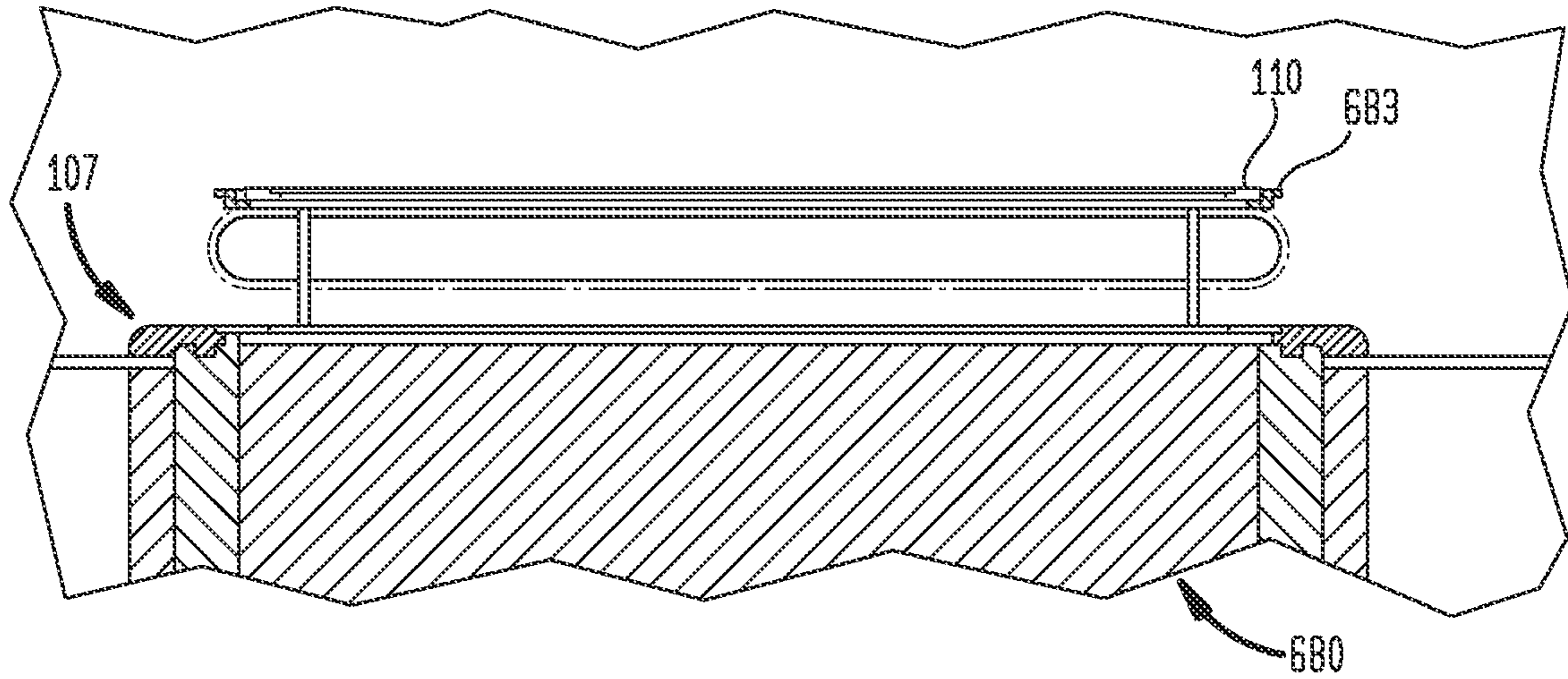


FIG. 6G

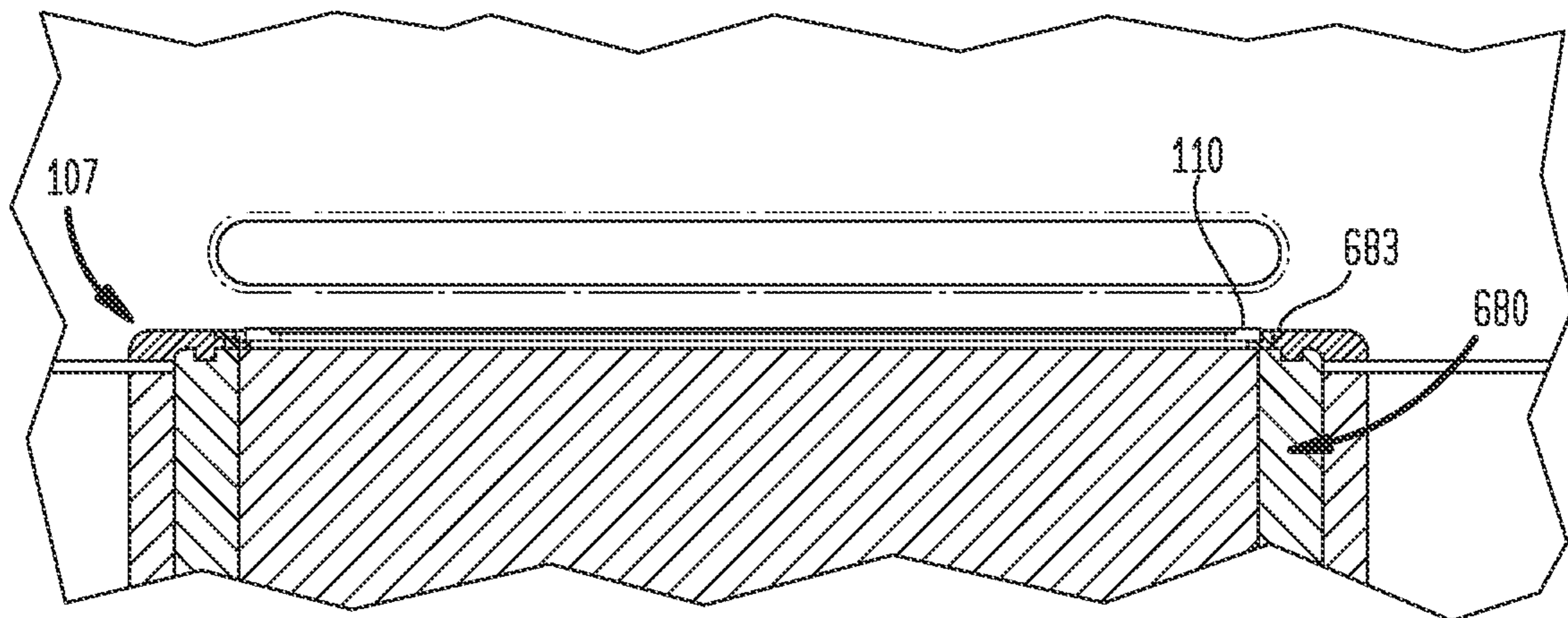


FIG. 6H

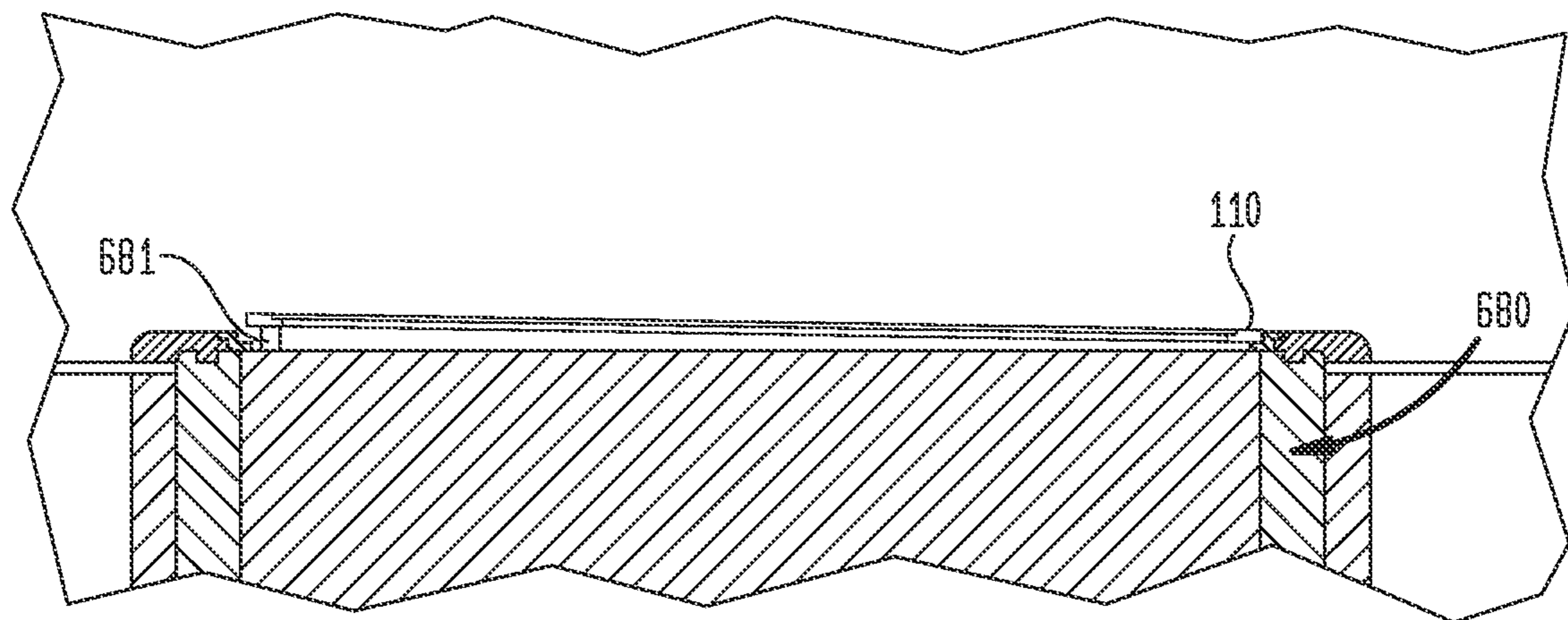


FIG. 6I

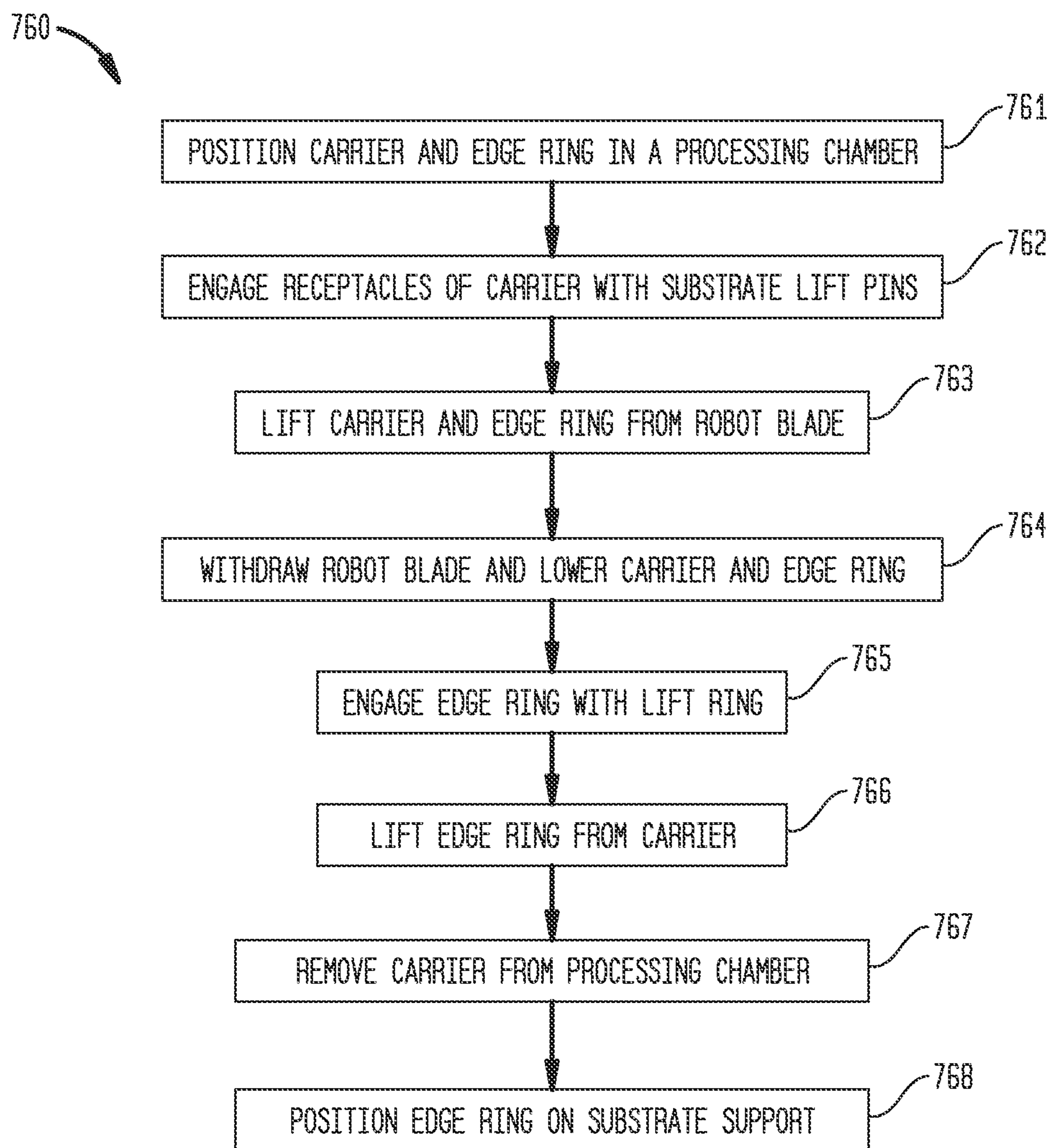


FIG. 7

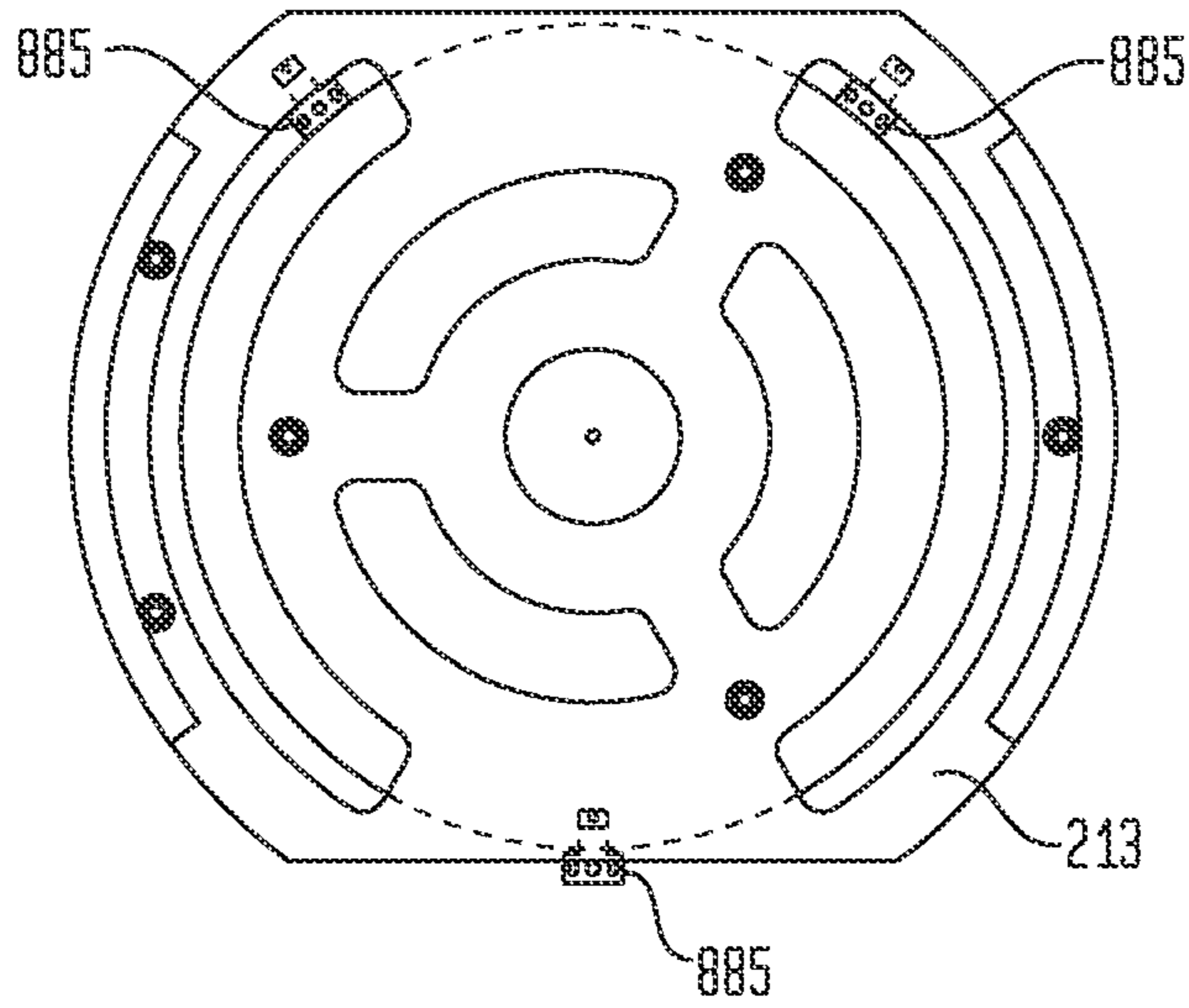


FIG. 8A

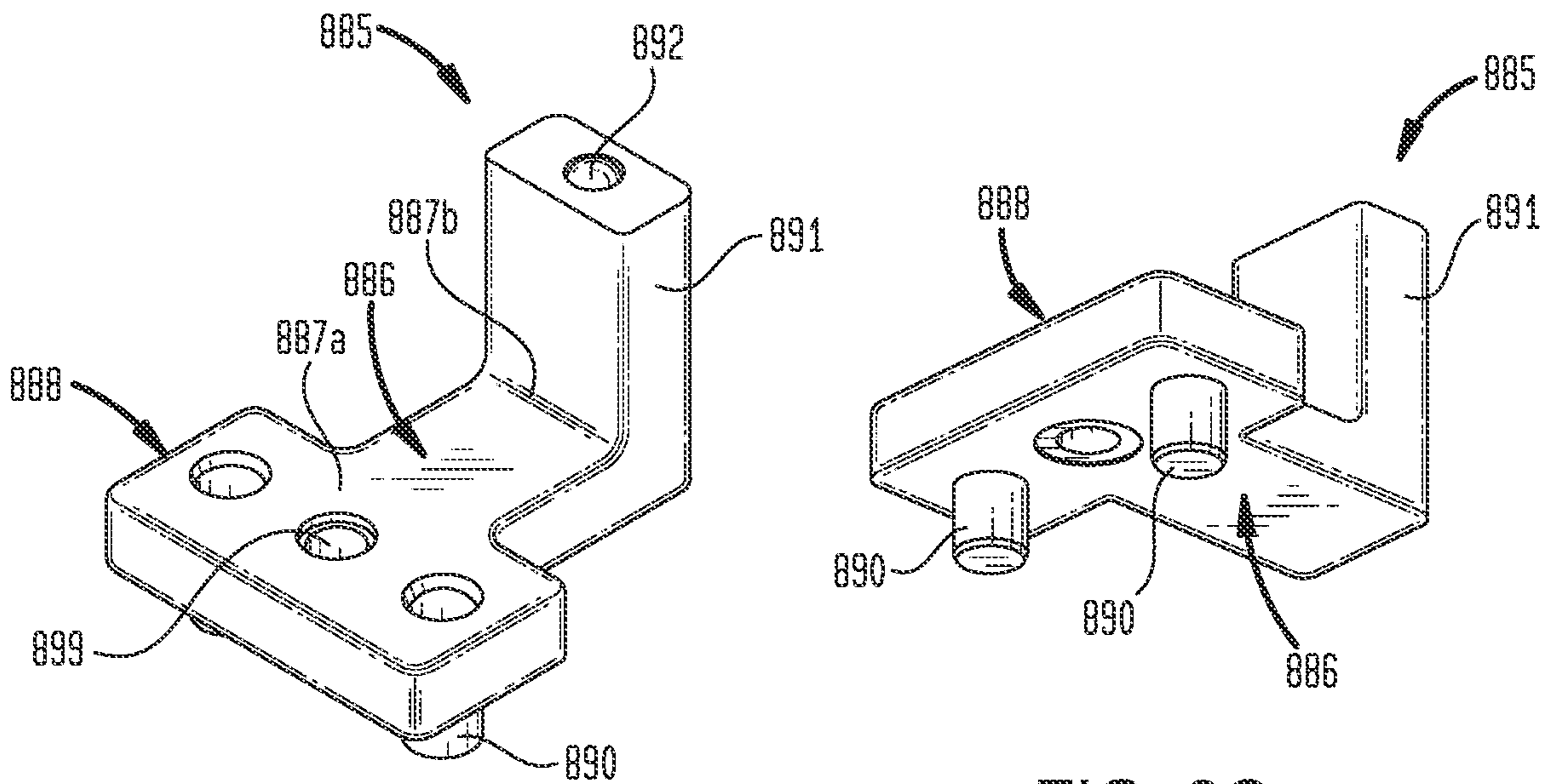


FIG. 8B

FIG. 8C

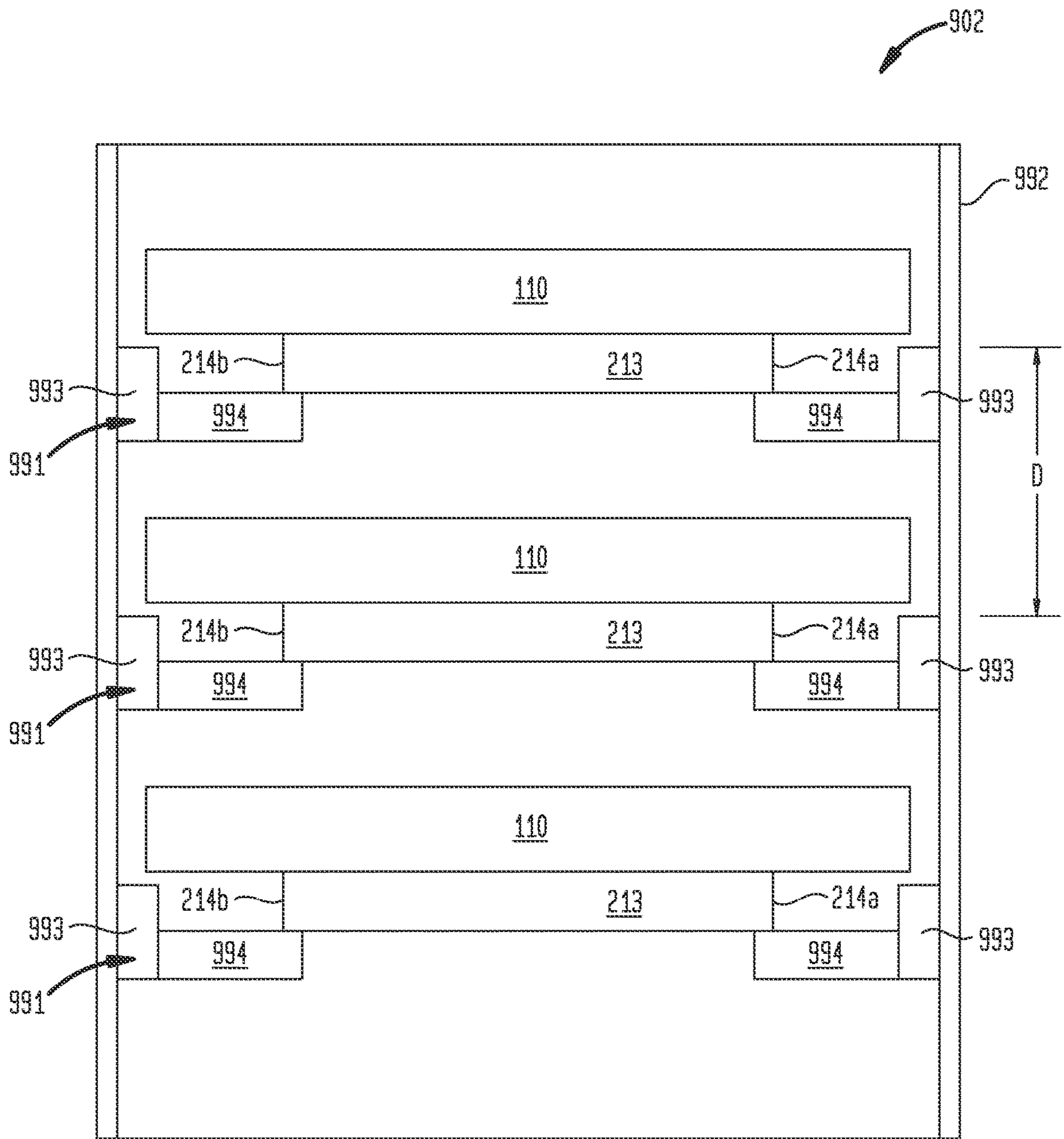


FIG. 9

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IN-SITU APPARATUS FOR SEMICONDUCTOR PROCESS MODULE

CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a continuation of U.S. patent application Ser. No. 16/103,531 filed Aug. 14, 2018, which claims benefit of U.S. Provisional Patent Application Ser. No. 62/561,463 filed Sep. 21, 2017, each of which is incorporated herein by reference in its entirety.

BACKGROUND

Field

Aspects of the present disclosure generally relate to apparatuses and methods for edge ring replacement in processing chambers, such as those used in semiconductor processing.

Description of the Related Art

In processing chambers, such as etch chambers, substrates are etched while electrostatically clamped in position. Typically, a circular part, referred to as an edge ring, is positioned immediately outside of the outer diameter of the substrate to protect the upper surface of the electrostatic chuck from being etched by etchant chemistry. Edge rings are made from several different materials and can have different shapes, both which affect process uniformity near the edge ring. During processing, edge rings are etched over time thereby resulting in shape changes as well as changes in processing uniformity.

To address the changes in processing uniformity due to edge ring deterioration, edge rings are changed according to a schedule. Conventionally, to replace an edge ring, processing chambers are opened to allow an operator to have access to the edge ring inside. However, this process is time consuming, and due to venting of the processing chambers, may take up to 24 hours to get processing back online.

Therefore, there is a need for new methods and apparatuses for replacing edge rings.

SUMMARY

Aspects of the present disclosure generally relate to apparatuses and methods for edge ring replacement in processing chambers.

In one aspect, a carrier for supporting an edge ring includes a plate having a perimeter including two opposing curved edges. The carrier further includes a first plurality of receptacles disposed in the plate with each configured to receive a lift pin therein, and a second plurality of receptacles disposed in the plate with each configured to engage a supporting structure. A first arcuate support structure is coupled to one of the two opposing curved edges, the first arcuate support structure extending above a plane of an upper surface of the plate. A second arcuate support structure is coupled to the other of the two opposing curved edges, the second arcuate support structure extending above the plane of the upper surface of the plate.

In another aspect, a robot blade includes a base and two fingers extending from the base. A base carrier engagement feature is coupled to an upper surface of the base, and finger carrier engagement features are each coupled to an upper surface of a respective one of the two fingers.

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In another aspect, a method of transferring an edge ring includes inserting a robot blade into a chamber through a slit valve door, the robot blade having a carrier and an edge ring thereon, positioning the carrier and the edge ring thereon over a substrate support, actuating substrate lift pins to lift the carrier from the robot blade, and retracting the robot blade from the chamber.

In another aspect, a carrier for supporting an edge ring comprises a semi-circular plate. The semi-circular plate has a perimeter defined by two parallel edges and two opposing curved edges coupling the two parallel edges. A first plurality of receptacles is disposed in the semi-circular plate, each receptacle configured to receive a lift pin therein. A second plurality of receptacles is disposed in the semi-circular plate, each receptacle configured to engage a supporting structure. A first arcuate support structure is coupled to one of the two opposing curved edges. The first arcuate support structure extends above a plane of an upper surface of the semi-circular plate. A second arcuate support structure is coupled to one of the two opposing curved edges, the second arcuate support structure extending above the plane of the upper surface of the semi-circular plate.

In another aspect, a robot blade comprises a base and two fingers extending from the base. The robot blade also includes two end pads, wherein one of the two end pads is disposed at each distal end of one of the two fingers. The robot blade also includes a base pad coupled to the base, and a roller configured to actuate from the base towards the two fingers.

In another aspect, a robot blade comprises a base having an elevated ridge formed on an upper surface thereof, and two fingers extending from the base. Each finger has elevated ridges formed on upper surfaces thereof at respective distal ends thereof, wherein the elevated ridges formed on upper surfaces of the two fingers and the elevated ridge formed on an upper surface of the base are arcs of a common circle. The robot blade also includes a plurality of engagement posts, wherein one of the plurality engagement posts is formed on an upper surface of the base, and one of the plurality of engagement posts is formed on upper surfaces of each of the two fingers.

In another aspect, a method of transferring an edge ring comprises inserting a robot blade into a chamber through a slit valve door, the robot blade having a carrier and an edge ring thereon. The carrier and the edge ring thereon are positioned over a substrate support, and substrate lift pins are actuated to lift the carrier from the robot blade. The robot blade is retracted from the chamber, and the substrate lift pins are actuated to lower the carrier toward the substrate support. A second set of lift pins are actuated to lift the edge ring from the carrier, and the robot blade is inserted in the chamber and engages the carrier. The carrier and the robot blade are removed from the chamber, and the edge ring is lowered into contact with the substrate support.

In another aspect a support structure for supporting a substrate carrier comprises a base having a first end and a second end, and a cross member disposed at the first end of the base. The cross member is disposed in a same plane as the base and having a width greater than the base. The cross member includes an opening formed therethrough, and at least two support posts extending from a surface of the cross member, the at least two support posts positioned on opposite sides of the opening. The support structure also includes a vertical member extending from the second end of the base. The vertical member extends in a direction opposite to

the at least two support posts of the cross member. The vertical member includes a ball bearing or contact pad at one end thereof.

BRIEF DESCRIPTION OF THE DRAWINGS

So that the manner in which the above recited features of the present disclosure can be understood in detail, a more particular description of the disclosure, briefly summarized above, may be had by reference to aspects, some of which are illustrated in the appended drawings. It is to be noted, however, that the appended drawings illustrate only exemplary aspects and are therefore not to be considered limiting of scope, as the disclosure may admit to other equally effective aspects.

FIG. 1 illustrates a processing system, according to one aspect of the disclosure.

FIG. 2A is a schematic top plan view of a carrier, according to one aspect of the disclosure. FIG. 2B is a schematic bottom plan view of the carrier of FIG. 2A. FIGS. 2C-2F are schematic sectional views of the carrier of FIG. 2A.

FIG. 3A is a schematic top plan view of a carrier supporting an edge ring thereon. FIG. 3B is a schematic sectional view of FIG. 3A.

FIGS. 4A and 4B are schematic top and bottom plan views, respectively, of a robot blade supporting a carrier thereon, according to one aspect of the disclosure. FIGS. 4C and 4D are schematic sectional views of a robot blade supporting a carrier thereon, according to one aspect of the disclosure.

FIG. 5A is a schematic perspective view of a robot blade, according to one aspect of the disclosure.

FIG. 5B is a schematic sectional view of the robot blade of FIG. 5A supporting a carrier, according to one aspect of the disclosure.

FIGS. 6A-6I schematically illustrate placement of an edge ring within a processing chamber, according to one aspect of the disclosure.

FIG. 7 is a flow diagram of a method of placing an edge ring, according to one aspect of the disclosure.

FIG. 8A is a schematic illustration of a carrier in a degassing chamber.

FIGS. 8B and 8C are schematic perspective views of a support finger, according to aspects of the disclosure.

FIG. 9 discloses a cassette, according to one aspect of the disclosure.

To facilitate understanding, identical reference numerals have been used, where possible, to designate identical elements that are common to the figures. It is contemplated that elements and features of one aspect may be beneficially incorporated in other aspects without further recitation.

DETAILED DESCRIPTION

Aspects of the present disclosure generally relate to apparatuses and methods for edge ring replacement in processing chambers. In one aspect, a carrier for supporting an edge ring is disclosed. In another aspect, one or more robot blades for supporting a carrier are disclosed. In another aspect, a support structure for supporting a carrier in a degassing chamber is disclosed. In yet another aspect, a method of transferring an edge ring on a carrier is disclosed.

FIG. 1 illustrates a processing system 100, according to one aspect of the disclosure. The processing system 100 includes a factory interface 101 to which a plurality of substrate cassettes 102 may be coupled for transferring

substrates into the processing system 100. The processing system 100 also includes first vacuum ports 103a, 103b coupling the factory interface 101 to respective degassing chambers 104a, 104b. Second vacuum ports 105a, 105b are coupled to respective degassing chambers 104a, 104b and disposed between the degassing chambers 104a, 104b and a transfer chamber 106 to facilitate transfer of substrates into the transfer chamber 106. The transfer chamber 106 includes a plurality of processing chambers 107 disposed therearound and coupled thereto. The processing chambers 107 are coupled to the transfer chamber 106 through respective ports 108, such as slit valves or the like. A controller 109 controls various aspects of the processing system 100.

The processing chambers 107 may include or more of etch chambers, deposition chambers (including atomic layer deposition, chemical vapor deposition, physical vapor deposition, or plasma enhanced versions thereof), anneal chambers, and the like. Some of the processing chambers 107, such as etch chambers, may include edge rings therein, which occasionally require replacement. While conventional systems require disassembly of a processing chamber by an operator to replace an edge ring, the processing system 100 is configured to facilitate replacement of edge rings without disassembly of a processing chamber 107 by an operator.

FIG. 1 schematically illustrates transfer of an edge ring 110 into a processing chamber 107. According to one aspect of the disclosure, an edge ring 110 is removed from a cassette 102 via factory interface robot 111 located in the factory interface 101, or alternatively, is loaded directly into the factory interface 101. The factory interface robot 111 transfers the edge ring 110 through one of the first vacuum ports 103a, 103b and into a respective degassing chamber 104a, 104b. A transfer chamber robot 112 located in the transfer chamber 106 removes the edge ring 110 from one of the degassing chambers 104a, 104b through a second vacuum port 105a or 105b. The transfer chamber robot 112 moves the edge ring 110 into the transfer chamber 106, where the edge ring 110 may be transferred to a desired processing chamber 107 through a respective port 108. While not shown for clarity in FIG. 1, transfer of the edge ring 110 occurs while the edge ring 110 is positioned on a carrier.

FIG. 1 illustrates one example of edge ring transfer, however, other examples are also contemplated. For example, it is contemplated that an edge ring may be manually loaded into the transfer chamber 106. From the transfer chamber 106, the edge ring 110 may be loaded into a processing chamber 107 by the transfer chamber robot 112. Additionally or alternatively, edge rings may be loaded in a substrate support pedestal (SSP). An additional SSP may be positioned in communication with the factory interface 101 opposite the illustrated SSP. It is contemplated that a processed edge ring 110 may be removed from the processing system 100 in reverse of any manner described herein. When utilizing two SSPs or multiple cassettes 102, it is contemplated that one SSP or cassette 102 may be used for unprocessed edge rings 110, while another SSP or cassette 102 may be used for receiving processed edge rings 110.

FIG. 2A is a schematic top plan view of a carrier 213, according to one aspect of the disclosure. FIG. 2B is a schematic bottom plan view of the carrier 213 of FIG. 2A. FIGS. 2C-2F are schematic sectional views of the carrier 213 of FIG. 2A. The carrier 213 is a semi-circular plate 216 having a perimeter defined by two parallel edges 214a, 214b and two opposing curved edges 215a, 215b coupling the two parallel edges 214a, 214b. The curved edges 215a, 215b facilitate lateral support of an edge ring positioned thereon, while the two parallel edges 214a, 214b allow the carrier

213 to be accommodated in processing chambers not originally designed to accommodate a carrier 213 therein. For example, the two parallel edges 214a, 214b facilitate actuation of lift pins within a processing chamber without interfering with the carrier 213 while the carrier 213 is located within the processing chamber.

The semi-circular plate 216 includes a central opening 217 and one or more semi-circular openings (three are shown) 218a positioned concentrically around the central opening 217. Additional semi-circular openings 218b are positioned concentrically about the one or more semi-circular openings 218a. The semi-circular openings 218a, 218b facilitate a reduction in weight of the carrier 213, allowing the carrier 213 to be used on existing transfer equipment not originally designed to handle weight in excess of semiconductor wafer weights. In one example, the semi-circular plate 216 is formed from one or more materials including carbon fiber, graphite, silicon carbide, graphite-coated-silicon-carbide, silicon nitride, silicon oxide, alumina, and the like. Other materials are also contemplated.

The semi-circular plate 216 also includes a first plurality of receptacles 219 disposed therein. The receptacles 219 are metallic caps disposed in bores formed through the semi-circular plate 216. The receptacles 219 are sized and configured to receive a lift pin therein to facilitate actuation of the carrier 213 within a processing chamber. The receptacles 219 are each located at the same radial distance from a center of the semi-circular plate 216. In one example, the receptacles 219 are positioned at a radius greater than a radius of the semi-circular openings 218a, but at a radius less than a radius of the semi-circular openings 218b.

FIGS. 2C and 2D are schematic sectional views of a receptacle 219. The receptacle 219 includes a body 220 having a cylindrical shape, and a flared base 221 at one end of the body. The body 220 is disposed through the semi-circular plate 216, while the flared base 221 is partially positioned in and contacts a counterbore formed on a lower surface of the semi-circular plate 216. The receptacle 219 includes a first recess 222 extending into the body 220, and a counterbore 223 formed in the flared base 221. The recess 222 and the counterbore 223 are coupled by a tapering sidewall 224 to facilitate feature engagement. In one example, the recess 222 has an oblong or parabolic shape to accommodate a diametrical alignment feature. In such an example, the recess 222 may have a greater width in a direction parallel to the two parallel edges 214a, 214b, as opposed to a direction perpendicular to the two parallel edges 214a, 214b. The parabolic or oblong shape of the recess 222 facilitates accommodation of the lift pin within the recess 222.

The semi-circular plate 216 also includes a second plurality of receptacles 225 (three are shown) disposed therein. The receptacles 225 are each configured to engage a supporting structure, such as a robot blade. Engagement of the receptacles 225 by the supporting structure reduces or prevents relative movement between the carrier 213 and the supporting structure during transfer of the carrier 213. For example, the supporting structure may include corresponding male plugs to be received within the receptacles 225.

The receptacles 225 include a body 226 disposed in an opening formed in the semi-circular plate 216. The receptacles 225 also include a flared portion 227 disposed at one end of the body 226. The flared portion 227 has a diameter greater than the body 226, and is partially disposed in a counterbore formed on the bottom side of the semi-circular plate 216. A bore 228 is formed through the body 226 and the flared portion 227, and includes countersinks 229 at

opposing ends thereof. The countersink 229 on a lower end thereof facilitates guiding of a male plug into the receptacle 225.

Each of the receptacles 219, 225 may be formed from one or more of a metal, silicon carbide, graphite, alumina, silicon nitride, silicon oxide, polyethylene terephthalate, or a ceramic material. Other materials are also contemplated. In one example the receptacles 219, 225 are formed from a soft polymer material, such as Vespel®, Ultem®, acetal, PTFE, or a ceramic material such as silicon carbide, to reduce particle generation.

The carrier 213 also includes a first arcuate support structure 230a coupled to the semi-circular plate 216 at the curved edge 215a, and a second arcuate support structure 230b coupled to the semi-circular plate 216 at the curved edge 215b. Each of the first arcuate support structure 230a and the second arcuate support structure 230b is disposed on an upper surface of the semi-circular plate 216. The first arcuate support structure 230a and the second arcuate support structure 230b extend above a plane of the upper surface of the semi-circular plate 216. In one example, each of the first arcuate support structure 230a and the second arcuate support structure 230b have a length less than length of a corresponding curved edge 215a, 215b. Each of the first arcuate support structure 230a and the second arcuate support structure 230b may be formed from a material such as carbon fiber, polyethylene terephthalate, or graphite.

Each of the first arcuate support structure 230a and the second arcuate support structure 230b include male extensions 231 that engage openings 232 formed through the semi-circular plate 216. FIG. 2F illustrates a section view of a male extension 231 and an opening 232. The extension 231 engages the opening 232 and is maintained therein via an interference fit. In one example, the openings 232, as well as the first arcuate support structure 230a and the second arcuate support structure 230b, are positioned radially outward of the receptacles 225. Each of the first arcuate support structure 230a and the second arcuate support structure 230b has a radius of curvature that is about equal to a radius of curvature of the curved edges 215a, 215b.

Referring back to FIG. 2F, each of the first arcuate support structure 230a and the second arcuate support structure 230b include stepped surfaces on radially outward edges thereof. Each stepped surface includes a supporting surface 233 positioned approximately parallel to an upper surface of the semi-circular plate 216, and a vertical wall 234 positioned radially inward of the supporting surface 233 and oriented about perpendicular to an upper surface of the semi-circular plate 216. An edge ring (shown in FIG. 3A) engages the supporting surface 233 and the vertical wall 234 while being supported on the carrier 213. In one example, the distance between vertical walls 234 of the opposing first arcuate support structure 230a and the second arcuate support structure 230b is about equal to an inner diameter of the an edge ring, thereby reducing or mitigating movement of the edge ring relative to the carrier 213 during a transfer process. In one example, the vertical walls 234 are positioned radially outward of the male extensions 231.

While FIGS. 2A-2F illustrate one example of a carrier 213, other examples are also contemplated. For example, the carrier 213 may have a completely circular body, rather than semi-circular. Additionally or alternatively, the carrier may include circular openings rather than semi-circular openings 218a, 218b. In another example, the semi-circular openings 218a, 218b may be excluded. In such an example, the carrier 213 may be formed, at least partially, from carbon fiber, a light-weight composite material, or another high-strength,

low-weight, vacuum-compatible material. In one example, the carrier **213** is symmetrical about one or more axis to mitigate imbalance during movement and placement of the carrier **213**. In another example, the first arcuate support structure **230a** and the second arcuate support structure **230b** include outer edges which taper inwards from a lower portion thereof to an upper portion, to facilitate engagement with and alignment of an edge ring **110**.

FIG. **3A** is a schematic top plan view of a carrier **213** supporting an edge ring **110** thereon. FIG. **3B** is a schematic sectional view of FIG. **3A**. As shown in FIG. **3A** and FIG. **3B**, the edge ring **110** is disposed on and supported by the first arcuate support structure **230a** and the second arcuate support structure **230b**. A lower surface of the edge ring **110** contacts the supporting surfaces **233**, while a radially inward edge of the edge ring **110** contacts the vertical walls **234** of the first arcuate support structure **230a** and the second arcuate support structure **230b**. In the illustrated example, the edge ring **110** has an inner diameter less than an outer diameter of the first arcuate support structure **230a** and the second arcuate support structure **230b**, and the edge ring **110** has an outer diameter greater than the outer diameters of the first arcuate support structure **230a** and the second arcuate support structure **230b**. Additionally, an upper surface of the edge ring **110** disposed above upper surfaces of the first arcuate support structure **230a** and the second arcuate support structure **230b**. In one example, one or both of the first arcuate support structure **230a** and the second arcuate support structure **230b** may include a feature, such as a flat surface, for engaging an electrostatic chuck or other substrate support to facilitate alignment therewith.

FIGS. **4A** and **4B** are schematic top and bottom plan views, respectively, of a robot blade **435** supporting the carrier **213** thereon, according to one aspect of the disclosure. FIGS. **4C** and **4D** are schematic sectional views of the robot blade **435** supporting the carrier **213** thereon, according to one aspect of the disclosure. The robot blade **435** may be used on the factory interface robot **111**. However, other uses are also contemplated.

The robot blade **435** includes a base **436** and one or more fingers **437** (e.g., two fingers **437** are shown) extending from the base **436**. In the example shown, the fingers **437** are palmated, but it is contemplated that discrete fingers **437** may be utilized. The base **436** may be coupled to an actuating arm of a robot to facilitate movement of the robot blade **435**. In one or more embodiments, a robot blade in accordance with the present disclosure may include one or more carrier engagement features to facilitate engaging and supporting the carrier **213** with a robot blade. For example, a robot blade may include a base carrier engagement feature, such as coupled to or formed on an upper surface of the base of the robot blade, and finger carrier engagement features, such as coupled to or formed on an upper surface of each finger of the robot blade. In the example shown, the robot blade **435** includes an end pad **438** disposed at a distal end of each finger **437** for carrier engagement features. The robot blade **435** also includes one or more base pads **439** (e.g., two pads **439** are shown) coupled to an upper surface the base **436** as a base carrier engagement feature. A roller **440** is also included with the robot blade **435** and is configured to actuate inward and outward (e.g., laterally) to/from the base **436** towards the two fingers **437**. The roller **440** is coupled to a sliding member **441** that moves relative to the base **436**. The roller **440** may rotate about a post or may be a non-rotating member, such as a bumper. An actuator (not shown) is configured to actuate the sliding member **441** and the roller **440** towards a distal end of the finger **437** to

facilitate securing of the carrier **213**. With reference to FIG. **4D**, the roller **440** is shown in a non-contact position, but may be actuated into contact with an outer edge of the carrier **213** to facilitate securing of the carrier **213**. In a contact position of the roller **440** and the carrier **213**, a gap is present between a bottom surface of the edge ring **110** and an upper surface of the roller **440** so that roller **440** may actuate without contacting the edge ring **110**, thereby reducing damage to the edge ring **110** as well as reducing particle generation.

The roller **440** is positioned between two base pads **439** disposed adjacent to or abutting the base **436**. An upper surface **490** of each base pad **439** is a supporting surface for the carrier **213**. Each base pad **439** includes a planar lower surface **442** disposed on an upper surface of the fingers **437** (or a palm thereof) at a proximal end thereof. The upper surface **490** of each base pad **439** includes a step **443** adjacent the base **436**, and a tapered portion **444** tapering downward from the step **443** towards a distal end of the fingers **437**. In one example, the carrier **213** rests upon the tapered portion **444** of the upper surface **490** during transport.

The fingers **437** additionally include end pads **438** disposed at distal ends thereof. The end pads **438** are formed from the same or similar material as the base pads **439**. The end pads **438** facilitate support of the carrier **213** at or near the end of the fingers **437**, and are sized and shaped to maintain the carrier **213** parallel to the fingers **437** during transport of the carrier **213**. In one example, the end pads **438** include a planar lower surface **445** in contact with the fingers **437**, and an upper surface having a planar portion **446a**, which contacts the carrier **213**, and a tapered portion **446b**, proximal the planar portion **446a**. In one example, a height of the base pads **439** and the end pads **438** are selected to provide spacing between a lower surface of receptacles **225** and an upper surface of the fingers **437**.

In one example, the roller **440**, each end pad **438**, and each base pad **439** is a padded material to reduce damage to the carrier **213**. In another example, the roller **440**, each end pad **438**, and each base pad **439** is formed from silicon oxide, silicon nitride, silicon carbide, or polyethylene terephthalate. The fingers **437** and the base **436** may be formed from a metal or metal alloy, such as aluminum, or a ceramic material, such as silicon carbide.

FIG. **5A** is a schematic view of a robot blade **548** and a robot wrist **549**, according to one aspect of the disclosure. FIG. **5B** is a sectional view of the robot blade **548** of FIG. **5A** supporting the carrier **213** and the edge ring **110**, according to one aspect of the disclosure. In one aspect, the robot blade **548** is configured to be coupled to existing robot wrists, or may be coupled to the robot wrist **549** by one or more fasteners **550**, such as bolts. In turn, the robot wrist **549** may be coupled to a robot to facilitate movement of the robot blade **548**. In one example, the robot blade **548**, and optionally the robot wrist **549**, may be utilized with the transfer chamber robot **112** (shown in FIG. **1**).

The robot blade **548** includes a base **551** adjacent a distal end of the robot wrist **549**. The base **551** has an elevated ridge **552** formed on an upper surface thereof. In one example, the elevated ridge **552** includes a stepped surface (not shown). The stepped surface may engage a carrier **213** during a transport operation to facilitate support of a carrier **213**, thereby providing extra support to the carrier **213**. The robot blade **548** also includes two fingers **554** extending from the base **551**. Each finger **554** has an elevated ridge **555** formed on an upper surface thereof at respective distal ends

thereof. Each elevated ridge **555** extends perpendicularly from the upper surface of each finger **554**.

The elevated ridges **555** of the fingers **554** and the elevated ridge **552** of the base **551** are configured in semi-circular or curved arrangement. In one example, the elevated ridges **555** formed on the upper surfaces of the two fingers **554** and the elevated ridge **552** formed on an upper surface of the base **551** are arcs of a common circle. In such an example, the common circle may be about the same size as the carrier **213** to facilitate support of the carrier **213**.

In addition to or as an alternative to support provided by the elevated ridge **552** and the elevated ridges **555**, the robot blade **548** may include a plurality of carrier engagement features, such as a plurality of engagement posts **556** (three are shown). In one example, the engagement posts **556** are cylindrical columns extending perpendicularly from an upper surface of the robot blade **548**. The base **551** includes one of the engagement posts **556** formed on an upper surface thereof adjacent the elevated ridge **552**, while each of the two fingers **554** includes a respective engagement post **556** disposed on a respective upper surface thereof.

As illustrated in FIG. **5B**, each engagement post **556** is positioned to engage a corresponding receptacle **225** of the carrier **213**. Engagement of the receptacles **225** by the engagement posts **556** reduces relative movement between the robot blade **548** and the carrier **213** during transport of the carrier **213**. When the receptacles **225** are engaged by the engagements posts **556**, an upper surface of the robot blade **548** is spaced from a lower surface of the semi-circular plate **216** of the carrier **213**. The dimensions of the receptacles **225** are selected to provide a gap between the upper surface of the robot blade **548** and the lower surface of the semi-circular plate **216**, thereby reducing contact between components and resulting in decreased particle generation.

In addition, the dimensions of the receptacles **225** may be selected to space a lower surface of the edge ring **110** from an upper surface of the elevated ridge **552** and the elevated ridges **555**, thereby reducing or eliminating contact between the edge ring **110** and the robot blade **548**. The reduced contact between the edge ring **110** and the robot blade **548** mitigates damage to the edge ring **110** caused by inadvertent contact with the robot blade **548**. Similarly, it is to be noted that the dimensions of the robot blade **548** may be selected to maintain spacing between an edge ring **110** and the robot wrist **549**, for similar reasons.

In some examples, the robot blade **548** may include one or more openings **557** formed therein. The one or more openings **557** facilitate weight reduction of the robot blade **548**, thereby compensating for the weight of the carrier **213**. In doing so, the robot blade **548** can be retrofitted to existing robots not originally designed for transfer of a carrier **213**. In one example, the robot blade **548** may also be used to transfer substrates. In such an example, the engagement posts **556** may include rounded upper surfaces to minimize contact with the substrate being transferred, thereby reducing particle generation.

FIGS. **6A-6H** schematically illustrate placement of an edge ring **110** with in a processing chamber **107**, according to one aspect of the disclosure. FIG. **7** is a flow diagram of a method **760** of placing an edge ring, according to one aspect of the disclosure. To facilitate explanation, FIG. **7** is explained in conjunction with FIGS. **6A-6H**.

FIG. **6A** schematically illustrates a top perspective view of an interior of a processing chamber **107**. The processing chamber **107** includes a port **108**, such as a slit valve, to facilitate ingress and egress of a robot blade **548** and robot wrist **549**. In operation **761** of method **760**, a carrier **213**

having an edge ring **110** thereon is positioned in a processing chamber **107** via the robot blade **548**. The carrier **213** and the edge ring **110** are centered over an electrostatic chuck of a substrate support **680**, as shown in FIG. **6A**. The dimensions of the carrier **213** are selected to allow the carrier **213** and the edge ring **110** to pass through the port **108** without requiring dimensional changes to the port **108**. Thus, the carrier **213** can be used on existing chambers without the need to significantly reconfigure dimensions of the processing chamber **107**. However, it is contemplated that dimensional changes to the port **108** may occur to provide additional clearance for ingress and egress of the carrier **213**.

In operation **762**, as shown in FIG. **6B**, substrate lift pins **681** (e.g., a first set of lift pins) are actuated into contact with receptacles **219** of the carrier **213**. In one example, three (3) substrate lift pins **681** are actuated such that each substrate lift pin **681** engages a respective receptacle **219**. The substrate lift pins **681** and the receptacles **219** are positioned to allow engagement therebetween without interference from the robot blade **548**. Subsequently, in operation **763**, the substrate lift pins **681** are actuated further upward to lift the carrier **213** and the edge ring **110** supported thereon from the robot blade **548**. In such a configuration, the carrier **213** and the edge ring **110** are positioned above and separated from the robot blade **548**, as shown in FIG. **6C**.

In operation **764**, the robot blade **548** is withdrawn from the processing chamber **107**, and the carrier **213** and the edge ring **110** are lowered towards the substrate support **680**, as shown in FIG. **6D**. In one example, the carrier **213** is lowered to a position that is spaced from an upper surface of the substrate support **680**, but is below a horizontal plane of the robot blade **548** or the initial engagement position of operation **762**.

In operation **765**, outer lift pins **682** (e.g., a second set of lift pins), located radially outward of the substrate lift pins **681**, actuate upward. The outer lift pins **682** are disposed below a lift ring **683**, and thus, when actuated upward, elevate the lift ring **683** form a surface of the substrate support **680**. The lift ring **683** is actuated upward via the outer lift pins **682** to contact a bottom surface of the edge ring **110**, as shown in FIG. **6E**. The lift ring **683** includes a stepped surface on an inner perimeter to receive the edge ring **110** therein. Alternatively, the lift ring **683** may include a tapered surface to facilitate alignment.

In operation **766**, the edge ring **110** is lifted from the carrier **213**, as shown in FIG. **6F**. For reference, FIG. **6F** shows a schematic side view that is rotated by about ninety degrees with respect to FIG. **6E** to show a different cross-section of the carrier **213**. The edge ring **110** is lifted by actuating the lift ring **683** further upward with the outer lift pins **682**. In operation **766**, the carrier **213** remains positioned on the substrate lift pins **681** while the edge ring **110** is lifted therefrom. In such a configuration, the carrier **213** is positioned in a first plane, and the lift ring **683** and the edge ring **110** located thereon are positioned in a second plane above the first plane. In one example, the carrier **213** may also optionally be lifted upward to align the carrier **213** with a port **108** to facilitate removal of the carrier **213** from the processing chamber **107**. In such an example, the lift ring **683** and the edge ring **110** are still positioned above the carrier **213**.

In operation **767**, the carrier **213** is removed from the processing chamber **107**, as shown in FIG. **6G**. The carrier **213** is removed by inserting the robot blade **584** back into the processing chamber **107** and lowering the carrier **213** onto the robot blade **584** using the substrate lift pins **681**. The substrate lift pins **681** are further lowered into the

substrate support **680** to reduce the likelihood of interference with the substrate lift pins **681**. With the carrier **213** positioned on the robot blade **584**, the robot blade **584** is withdrawn from the processing chamber **107**.

The parallel edges **214a**, **214b** (shown in FIG. 2A) provide clearance with respect to the outer lift pins **682**, allowing the carrier **213** to be withdrawn from the processing chamber **107** while the outer lift pins **682** remain extended in a vertically-lifted position. The carrier **213** can be withdrawn separate from the edge ring **110**, as described, thus leaving the edge ring **110** in the processing chamber **107**.

In operation **768**, with the carrier **213** and the robot blade **584** removed from the processing chamber **107**, the lift ring **683** and the edge ring **110** are positioned on the substrate support **680**, as shown in FIG. 6H. In such an example, the lift ring **683** is lowered downward via actuation of the outer lift pins **682** until the lift ring **683** is in contact with the substrate support **680**, thus positioning the edge ring **110** in a predetermined location. In one example, the edge ring **110** may include an alignment tab or other indexing feature to facilitate proper alignment of the edge ring **110** on the substrate support **680**.

In an alternative example to FIG. 6H, shown in FIG. 6I, the edge ring **110** may be disposed on the substrate support **680** such that one or more lift pins **681** positions the edge ring **110** in a non-parallel configuration with respect to an upper surface of the substrate support **680** for processing. For example, a lift pin **681** may lift one section of the edge ring **110** to a relative height (with respect to the substrate support **680**) greater than another section of the edge ring **110**. In doing so, a plasma sheath adjacent the substrate support **680** is affected. Thus, the position of the edge ring **110** may be chosen to affect the plasma sheath in order to result in more uniform processing.

While FIG. 7 illustrates one example of a method of transferring the edge ring **110**, other examples are also contemplated. For example, it is contemplated that an edge ring **110** may be removed from the processing chamber **100** by performing the method **670** in reverse.

In addition, it is contemplated that aspects of the present disclosure may be utilized to further adjust plasma uniformity. In one example, the outer lift pins **682** may adjust the planarity of the edge ring **110** with respect to the substrate support **680** once the edge ring **110** is positioned on the substrate support **680**. For example, after operation **768**, small adjustments may be made to the plane of the edge ring **110** by adjusting the vertical position of one or more of the outer lift pins **682** to affect the plasma sheath and/or chemistry in a specific location near the edge ring **110** (or a substrate being processed). In such an example, substrate processing may occur with the edge ring **110** being non-planar with respect to a substrate surface.

FIG. 8A is a schematic illustration of the carrier **213** when in use within a degassing chamber, such as the degassing chamber **104a** (shown in FIG. 1). FIG. 8B and FIG. 8C are schematic perspective views of a support structure **885** used within the degassing chamber, according to aspects of the disclosure.

The interior of the degassing chamber includes a plurality of support structures **885** (three are shown). The support structures **885** are configured to support substrates, such as semiconductor wafers, or carriers thereon, during a degassing operation. The support structures **885** are oriented and configured to support semiconductor wafers, which generally have a circular shape, as well as the substrate carrier **213**, which has a semi-circular shape.

Each support structure **885** includes a base **886** having a first end **887a** and a second end **887b**. A cross-member **888** is disposed at the first end **887a** of the base **886**. The cross-member **888** is disposed in the same plane as the base **886**, sharing a coplanar upper surface therewith. The cross-member **888** has a width greater than the base **886** and is oriented perpendicular to the base **886**. The cross-member **888** includes an opening **889** formed therethrough, and at least two support posts **890** extending from a lower surface of the cross member **888**. The two support posts **890** are positioned on opposite sides of the opening **889** and may have a cylindrical shape. In one example, the support posts **890** are axially movable or adjustable with respect to the cross-member **888**.

The support structure **885** also includes a vertical member **891** extending from the second end **887b** of the base **886**. The vertical member **891** extends in a direction parallel to the axis of the support posts **890**. In one example, the vertical member **891** extends in a direction opposite to the two support posts **890** relative to or from the base **886**. The vertical member **891** includes a ball bearing **892** at a distal end thereof. In another example, the vertical member **891** includes a contact pad at a distal end thereof. The ball bearing **891** (or contact pad) facilitates contact with a substrate without marring the surface of the substrate. The contact pad or the ball bearing **892** may be formed from ceramic or another material that mitigates particle generation. In one example, a contact pad or the ball bearing **892** is configured to support a substrate thereon during processing.

During operation, a substrate, such as a semiconductor wafer, is transferred into the degassing chamber **104a** and positioned on support structures **885**. Due to the size and shape of the substrate, the substrate is able to contact all ball bearings **892** of the support structures **895**. However, due to the semicircular shape of a carrier **213**, a carrier **213** is unable to contact all ball bearings **892** of the support structures **895**. However, the carrier **213** is able to contact the upper surface of the base **886** and the cross-member **888** of each support structure **885**, thereby allowing the support structures to support both semiconductor substrates as well as the carriers **213**.

Referring to FIG. 8A, to facilitate support of multiple substrates, the orientation of the support structures **885** is adjustable. In the illustrated example, two support members **885** are oriented such that the vertical member **891** is located radially inward, while a third support member **895** is oriented such that a respective vertical member **891** is located radially outward (e.g., 180 degrees with respect to one another). It is contemplated that each support member **895** may be rotated about an axis of the opening **889** to position each support member **895** in a desired configuration. The support posts **890** may engage a corresponding receptacle to prevent further rotational movement of each support member **895** when each support member **895** is in a desired location.

FIGS. 8A-8C illustrate one aspect of the disclosure, however, other aspects are also contemplated. In an alternative example, a degassing chamber **104a** may include more than three support structures **885**.

FIG. 9 discloses a cassette **902**, according to one aspect of the disclosure. The cassette **902** is configured to house one or more carriers **213** each having an edge ring **110** thereon (three of each are shown). Each carrier **213** is positioned on a comb **991**, spaced from one another by a distance "D". The distance D is selected to a desired amount of robot clearance within the cassette **902**. Each comb **991** includes opposing

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support structures coupled to internal surfaces of a housing 992. Each support structure includes a base 993 coupled to the housing 992, and an extension 994 that extends inward from a respective base 993 in a stepped configuration.

Carriers 213 of the present disclosure have opposing parallel edges 214a, 214b, and thus are not circular, which prevents support in conventional cassettes. However, the cassettes 902 of the present disclosure include extensions 994 extending radially inward to support a respective carrier 213 along the opposing parallel edges 214a, 214b. The stepped surface of each comb 991 prevents interference with an edge ring 110 when supporting a carrier 213 thereon. In one example, the size and position of the bases 993 of the combs 991 may be selected to allow support of a substrate, such as semiconductor wafer, thereon. Thus, the cassette 902 may be used both for introducing the carrier 213 and edge ring 110 to a processing system 100, as well as for introducing substrates to the processing system 100 for processing. In another example, a conventional cassette may be modified to include the extensions 994.

Benefits of the disclosure include having the ability to replace an edge ring without venting and opening a processing chamber. Because venting is avoided, chamber uptime is improved and maintenance costs are reduced. Moreover, replacing an edge ring without opening a processing chamber enables selection of edge ring shape or material to optimize performance of a specific etch application. Because conventional approaches require a significant amount of time to exchange edge rings for specific applications, doing so with conventional systems is impractical. However, because edge rings can be quickly exchanged or replaced using aspects described herein, it is now feasible to swap edge rings as dictated by process parameters.

Moreover, processing uniformity is also improved by aspects described herein. Because conventional approaches require significantly longer to replace edge rings, the time between preventative maintenance of edge rings is maximized in conventional systems to mitigate downtime. However, doing so results in well-worn edge rings immediately prior to the preventative maintenance. Because the shape and material of an edge ring affects the plasma sheath and chemistry concentrations near the edge of the substrate being processed, processing uniform may decrease due to the presence of a well-worn edge ring. However, because aspects of the present disclosure allow edge rings to be quickly replaced when beginning to wear, edge rings can be replaced more frequently without significant downtime, thereby leading to greater process uniformity.

While aspects herein are described with respect to semi-circular plates and carriers, it is contemplated that the carriers may be completely circular.

While the foregoing is directed to aspects of the present disclosure, other and further aspects of the disclosure may be devised without departing from the basic scope thereof, and the scope thereof is determined by the claims that follow.

What is claimed is:

1. A carrier for supporting an edge ring, comprising:
 - a plate having a perimeter including a plurality of curved edges and a plurality of parallel edges;
 - a plurality of inserts disposed in the plate, each insert formed of a polymer material and configured to engage a supporting structure; and
 - a plurality of support structures coupled to the plurality of curved edges, each respective support structure extending above a plane of an upper surface of the plate, and each respective support structure comprising:

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a step formed on a radially outward edge of the respective support structure and disposed above and below the plane of the upper surface of the plate, the step of each respective support structure comprising:

- a supporting surface disposed parallel to and below the upper surface of the plate, and
- an arcuate wall positioned radially inward of the supporting surface of the respective support structure and oriented perpendicular to and extending above the plane of the upper surface of the plate, the arcuate wall of each respective support structure extending perpendicularly to the supporting surface of the respective support structure, and
- a male extension positioned radially inward of the wall and extending into the plate.

2. The carrier of claim 1, wherein the arcuate wall of each respective support structure has a radius of curvature that is less than an inner radius of the edge ring.

3. The carrier of claim 2, wherein the arcuate wall of each respective support structure is disposed at a radius relative to a center of the plate, and the radius is equal to or lesser than the inner radius of the edge ring.

4. The carrier of claim 1, wherein the plate is a semi-circular plate.

5. The carrier of claim 1, wherein at least some of the plurality of inserts are positioned radially inward of the plurality of support structures.

6. The carrier of claim 1, wherein each insert comprises a body disposed in an opening formed in the plate.

7. The carrier of claim 6, wherein the body of each insert comprises a flared portion having an outer diameter that is larger than a cylindrical portion of the body.

8. The carrier of claim 7, wherein the body of each insert further comprises a bore formed through the body.

9. The carrier of claim 1, wherein the plate comprises one or more openings formed therein.

10. The carrier of claim 9, where the one or more openings comprises a plurality of openings, and at least one of the plurality of inserts is positioned between two of the plurality of openings.

11. A carrier for supporting an edge ring, comprising:

- a plate having a perimeter including a plurality of curved edges and a plurality of parallel edges;
- a plurality of inserts disposed in the plate, each insert formed of a polymer material and configured to engage a supporting structure; and
- a plurality of support structures coupled to the plurality of curved edges, each respective support structure comprising:

a step formed on a radially outward edge of the respective support structure, the step of each respective support structure comprising:

- a supporting surface, and
- an arcuate wall positioned radially inward of the supporting surface of the respective support structure and extending perpendicularly to the supporting surface of the respective support structure.

12. The carrier of claim 11, wherein the arcuate wall of each respective support structure has a radius of curvature that is less than an inner radius of the edge ring.

13. The carrier of claim 12, wherein the arcuate wall of each respective support structure is disposed at a radius relative to a center of the plate, and the radius is equal to or lesser than the inner radius of the edge ring.

14. The carrier of claim 11, wherein the plate is a semi-circular plate.

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15. The carrier of claim **11**, wherein each insert comprises a body disposed in an opening formed in the plate, and the body of each insert comprises a flared portion having an outer diameter that is larger than a cylindrical portion of the body.

16. The carrier of claim **15**, wherein the body of each insert further comprises a bore formed through the body.

17. A method of transferring an edge ring, comprising: inserting a robot blade into a chamber through a slit valve door, the robot blade having a carrier thereon and an edge ring supported on the carrier;

positioning the carrier and the edge ring thereon over a substrate support;

actuating substrate lift pins to lift the edge ring from the carrier; and

retracting the robot blade and the carrier from the chamber;

wherein the carrier comprises:

a plate having a perimeter including a plurality of curved edges and a plurality of parallel edges;

a plurality of inserts disposed in the plate, each insert formed of a polymer material and configured to engage a supporting structure; and

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a plurality of support structures coupled to the plurality of curved edges, each respective support structure comprising:

a step formed on a radially outward edge of the respective support structure, the step of each respective support structure comprising:

a supporting surface, and

an arcuate wall positioned radially inward of the supporting surface of the respective support structure and extending perpendicularly to the supporting surface of the respective support structure.

18. The method of claim **17**, further comprising: lowering the edge ring into contact with the substrate support.

19. The method of claim **18**, wherein lowering the edge ring into contact with the substrate support includes positioning the edge ring in a non-parallel configuration with respect to an upper surface of the substrate support to adjust a position of a plasma sheath during processing.

20. The method of claim **17**, wherein the inserts of the carrier are engaged with the robot blade during the inserting the robot blade into the chamber and the retracting the robot blade and the carrier from the chamber.

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